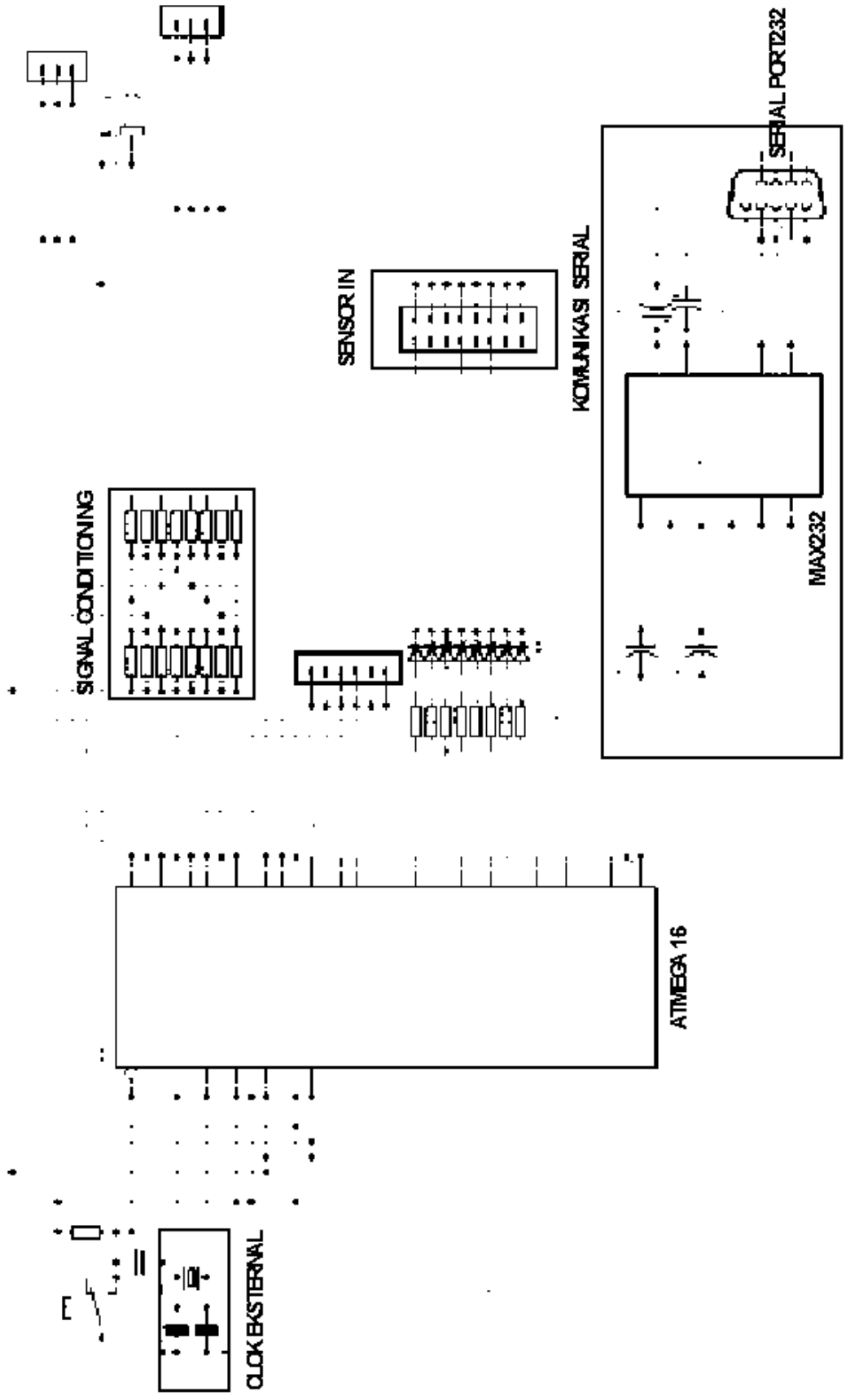
Lampiran A
Skematik Rangkaian



Gambar A.2. Skematik Rangkaian

Lampiran B

Listing Program Pada CodeVision AVR

```
/*****************************************************

This program was produced by the
CodeWizardAVR V1.25.3 Professional
Automatic Program Generator
© Copyright 1998-2007 Pavel Haiduc, HP InfoTech s.r.l.
http://www.hpinfotech.com

Project :
Version :
Date    : 1/31/2012
Author  : F4CG
Company : F4CG
Comments:


Chip type           : ATmega16
Program type        : Application
Clock frequency     : 14.745600 MHz
Memory model        : Small
External SRAM size  : 0
Data Stack size     : 256
*****************************************************/



#include <mega16.h>

// Standard Input/Output functions

#include <stdio.h>
#define ADC_VREF_TYPE 0x00
// Read the AD conversion result

unsigned int read_adc(unsigned char adc_input)

{
ADMUX=adc_input | (ADC_VREF_TYPE & 0xff);
// Start the AD conversion
ADCSRA|=0x40;
// Wait for the AD conversion to complete
while ((ADCSRA & 0x10)==0);
ADCSRA|=0x10;
return ADCW;
}
 //function declare



int baca(int n);
void MIDI_TX(unsigned char MESSAGE, unsigned char PITCH, unsigned char
VELOCITY);
int i, x, b;
//variable umum

unsigned char PadNote[8] = {42,38,45,35,41,47,52,57};         // MIDI notes
from 0 to 127 (Mid C = 60)

int PadCutOff = 100;           // Nilai ADC minimum yang akan diproses
```

```
int MaxPlayTime = 90;                // counter untuk pembacaan pukulan
berikutnya

#define midichannel   0;                                  // MIDI channel from 0
to 15 (+1 in "real world")
int VelocityFlag  = 1;               // Velocity ON (1) or OFF (0)

//variable acc
int activePad= 0;                   // Array of flags of pad currently
playing

int PinPlayTime = 0;                // Counter since pad started to play
int pin;
int hitavg;


// Declare your global variables here
void main(void)

{

// Declare your local variables here

// Input/Output Ports initialization
// Port A initialization
// Func7=In Func6=In Func5=In Func4=In Func3=In Func2=In Func1=In Func0=In
// State7=T State6=T State5=T State4=T State3=T State2=T State1=T State0=T
PORTA=0x00;
DDRA=0x00;

// Port B initialization
// Func7=In Func6=In Func5=In Func4=In Func3=In Func2=In Func1=In Func0=In
// State7=T State6=T State5=T State4=T State3=T State2=T State1=T State0=T
PORTB=0x00;
DDRB=0x00;

// Port C initialization
// Func7=In Func6=In Func5=In Func4=In Func3=In Func2=In Func1=In Func0=In
// State7=T State6=T State5=T State4=T State3=T State2=T State1=T State0=T
PORTC=0x00;
DDRC=0x00;

// Port D initialization
// Func7=In Func6=In Func5=In Func4=In Func3=In Func2=In Func1=In Func0=In
// State7=T State6=T State5=T State4=T State3=T State2=T State1=T State0=T
PORTD=0x00;
DDRD=0x00;

// Timer/Counter 0 initialization
// Clock source: System Clock
// Clock value: Timer 0 Stopped
// Mode: Normal top=FFh
// OC0 output: Disconnected
TCCR0=0x00;
TCNT0=0x00;
OCR0=0x00;

// Timer/Counter 1 initialization
// Clock source: System Clock
// Clock value: Timer 1 Stopped
// Mode: Normal top=FFFFh
```

```
// OC1A output: Discon.
// OC1B output: Discon.
// Noise Canceler: Off
// Input Capture on Falling Edge
// Timer 1 Overflow Interrupt: Off
// Input Capture Interrupt: Off
// Compare A Match Interrupt: Off
// Compare B Match Interrupt: Off

TCCR1A=0x00;
TCCR1B=0x00;
TCNT1H=0x00;
TCNT1L=0x00;
ICR1H=0x00;
ICR1L=0x00;
OCR1AH=0x00;
OCR1AL=0x00;
OCR1BH=0x00;
OCR1BL=0x00;

// Timer/Counter 2 initialization
// Clock source: System Clock
// Clock value: Timer 2 Stopped
// Mode: Normal top=FFh
// OC2 output: Disconnected

ASSR=0x00;
TCCR2=0x00;
TCNT2=0x00;
OCR2=0x00;

// External Interrupt(s) initialization
// INT0: Off
// INT1: Off
// INT2: Off
MCUCR=0x00;
MCUCSR=0x00;

// Timer(s)/Counter(s) Interrupt(s) initialization
TIMSK=0x00;

// USART initialization
// Communication Parameters: 8 Data, 1 Stop, No Parity
// USART Receiver: On
// USART Transmitter: On
// USART Mode: Asynchronous
// USART Baud rate: 57600
UCSRA=0x00;
UCSRB=0x18;
UCSRC=0x86;
UBRRH=0x00;
UBRRL=0x0F;

// Analog Comparator initialization
// Analog Comparator: Off
// Analog Comparator Input Capture by Timer/Counter 1: Off
ACSR=0x80;
SFIOR=0x00;

// ADC initialization
// ADC Clock frequency: 921.600 kHz
```

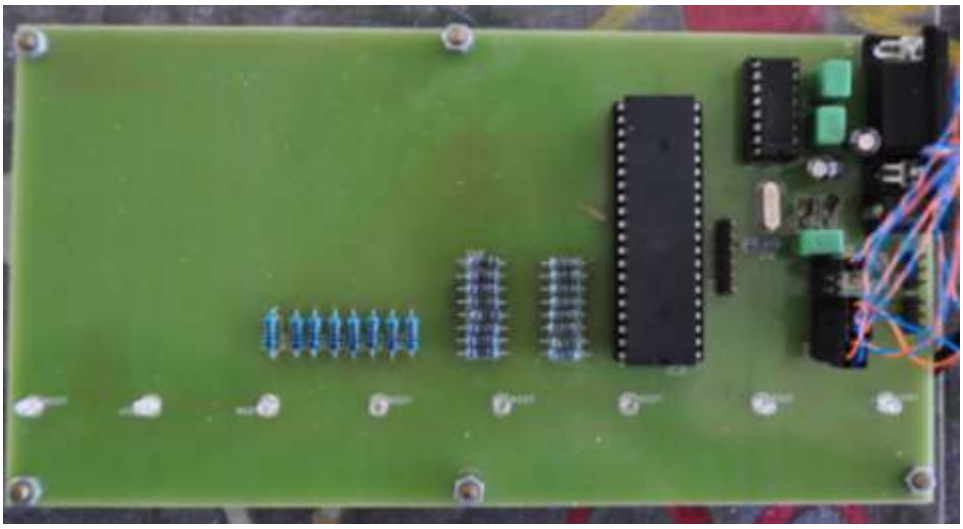
```
// ADC Voltage Reference: AREF pin
// ADC Auto Trigger Source: None
ADMUX=ADC_VREF_TYPE & 0xff;
ADCSRA=0x84;

while (1)
      {for(pin=0; pin < 8; pin++)
        {hitavg = read_adc(pin);                          // read the input pin
          if((hitavg>PadCutOff[pin]))
          { hitavg=baca(pin);
            if((activePad[pin] == 0))
            {
              if(VelocityFlag == 1)
              {
                hitavg = (hitavg / 8) -1 ;
              }
              else
              {
                hitavg = 127;
              }
             MIDI_TX(153,PadNote,hitavg);
             PinPlayTime = 0;
             activePad = 1;
           }
           else
           {
           PinPlayTime = PinPlayTime + 1;
           }
         }
        else if((activePad == 1))
         {
          PinPlayTime = PinPlayTime + 1;

                if(PinPlayTime >MaxPlayTime)
                {
                        activePad = 0;
                        MIDI_TX(139,PadNote[pin],127);
         }
        }
  }
      // Place your code here
      };
}
int baca(int n)
{x=0;
         for(i=0;i<100;i++)
        {
         b=read_adc(n);
        if(x<b) x=b;
        }
        return x;
 }

 void MIDI_TX(unsigned char MESSAGE, unsigned char PITCH, unsigned char
VELOCITY)
{
printf("%c",MESSAGE);
printf("%c",PITCH);
printf("%c",VELOCITY);
}
```

Lampiran C
Foto Alat

Gambar C – 1. MIDI Drum Pad Tampak Atas

Gambar C – 2. MIDI Drum Pad Tampak Samping

Gambar C – 3. Penempatan dan Dudukan Sensor



Gambar C – 4. Rangkaian Mikrokontroler

Lampiran D
Tabel MIDI

MIDI MANUFACTURERS ASSOCIATION

Table 1: MIDI 1.0 Specification Message Summary		
Status D7----D0	**Data Byte(s) D7----D0**	**Description**
Channel Voice Messages [nnnn = 0-15 (MIDI Channel Number 1-16)]		
1000nnnn	0kkkkkkk 0vvvvvvv	Note Off event. This message is sent when a note is released (ended). (kkkkkkk) is the key (note) number. (vvvvvvv) is the velocity.
1001nnnn	0kkkkkkk 0vvvvvvv	Note On event. This message is sent when a note is depressed (start). (kkkkkkk) is the key (note) number. (vvvvvvv) is the velocity.
1010nnnn	0kkkkkkk 0vvvvvvv	Polyphonic Key Pressure (Aftertouch). This message is most often sent by pressing down on the key after it "bottoms out". (kkkkkkk) is the key (note) number. (vvvvvvv) is the pressure value.
1011nnnn	0ccccccc 0vvvvvvv	Control Change. This message is sent when a controller value changes. Controllers include devices such as pedals and levers. Controller numbers 120-127 are reserved as "Channel Mode Messages" (below). (ccccccc) is the controller number (0-119). (vvvvvvv) is the controller value (0-127).
1100nnnn	0ppppppp	Program Change. This message sent when the patch number changes. (ppppppp) is the new program number.
1101nnnn	0vvvvvvv	Channel Pressure (After-touch). This message is most often sent by pressing down on the key after it "bottoms out". This message is different from polyphonic after-touch. Use this message to send the single greatest pressure value (of all the current depressed keys). (vvvvvvv) is the pressure value.
1110nnnn	0lllllll 0mmmmmmm	Pitch Wheel Change. 0mmmmmmm This message is sent to indicate a change in the pitch wheel. The pitch wheel is measured by a fourteen bit value. Center (no pitch change) is 2000H. Sensitivity is a function of the transmitter. (lllllll) are the least significant 7 bits. (mmmmmm) are the most significant 7 bits.

Table 2: Expanded Status Bytes List			
STATUS BYTE		**DATA BYTES**	
1st Byte Value **Binary |Hex| Dec**	**Function**	**2nd Byte**	**3rd Byte**
10000000= 80= 128	Chan 1 Note off	Note Number (0-127)	Note Velocity (0-127)
10000001= 81= 129	Chan 2 Note off	Note Number (0-127)	Note Velocity (0-127)
10000010= 82= 130	Chan 3 Note off	Note Number (0-127)	Note Velocity (0-127)
10000011= 83= 131	Chan 4 Note off	Note Number (0-127)	Note Velocity (0-127)
10000100= 84= 132	Chan 5 Note off	Note Number (0-127)	Note Velocity (0-127)
10000101= 85= 133	Chan 6 Note off	Note Number (0-127)	Note Velocity (0-127)
10000110= 86= 134	Chan 7 Note off	Note Number (0-127)	Note Velocity (0-127)
10000111= 87= 135	Chan 8 Note off	Note Number (0-127)	Note Velocity (0-127)
10001000= 88= 136	Chan 9 Note off	Note Number (0-127)	Note Velocity (0-127)
10001001= 89= 137	Chan 10 Note off	Note Number (0-127)	Note Velocity (0-127)
10001010= 8A= 138	Chan 11 Note off	Note Number (0-127)	Note Velocity (0-127)
10001011= 8B= 139	Chan 12 Note off	Note Number (0-127)	Note Velocity (0-127)
10001100= 8C= 140	Chan 13 Note off	Note Number (0-127)	Note Velocity (0-127)
10001101= 8D= 141	Chan 14 Note off	Note Number (0-127)	Note Velocity (0-127)
10001110= 8E= 142	Chan 15 Note off	Note Number (0-127)	Note Velocity (0-127)
10001111= 8F= 143	Chan 16 Note off	Note Number (0-127)	Note Velocity (0-127)
10010000= 90= 144	Chan 1 Note on	Note Number (0-127)	Note Velocity (0-127)
10010001= 91= 145	Chan 2 Note on	Note Number (0-127)	Note Velocity (0-127)
10010010= 92= 146	Chan 3 Note on	Note Number (0-127)	Note Velocity (0-127)
10010011= 93= 147	Chan 4 Note on	Note Number (0-127)	Note Velocity (0-127)
10010100= 94= 148	Chan 5 Note on	Note Number (0-127)	Note Velocity (0-127)
10010101= 95= 149	Chan 6 Note on	Note Number (0-127)	Note Velocity (0-127)
10010110= 96= 150	Chan 7 Note on	Note Number (0-127)	Note Velocity (0-127)
10010111= 97= 151	Chan 8 Note on	Note Number (0-127)	Note Velocity (0-127)
10011000= 98= 152	Chan 9 Note on	Note Number (0-127)	Note Velocity (0-127)
10011001= 99= 153	Chan 10 Note on	Note Number (0-127)	Note Velocity (0-127)
10011010= 9A= 154	Chan 11 Note on	Note Number (0-127)	Note Velocity (0-127)
10011011= 9B= 155	Chan 12 Note on	Note Number (0-127)	Note Velocity (0-127)
10011100= 9C= 156	Chan 13 Note on	Note Number (0-127)	Note Velocity (0-127)
10011101= 9D= 157	Chan 14 Note on	Note Number (0-127)	Note Velocity (0-127)
10011110= 9E= 158	Chan 15 Note on	Note Number (0-127)	Note Velocity (0-127)
10011111= 9F= 159	Chan 16 Note on	Note Number (0-127)	Note Velocity (0-127)

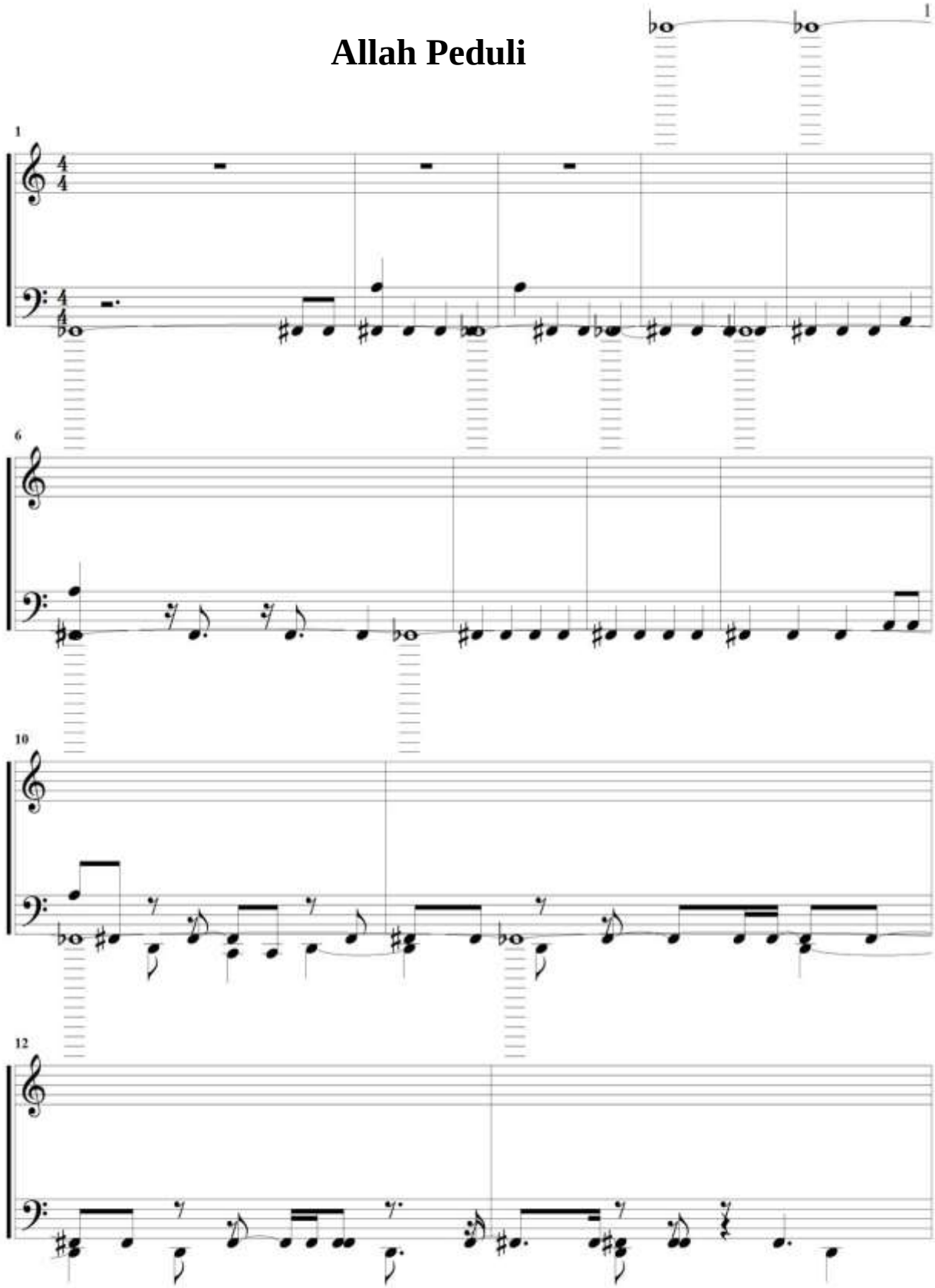
MIDI Percussion Pitch Byte

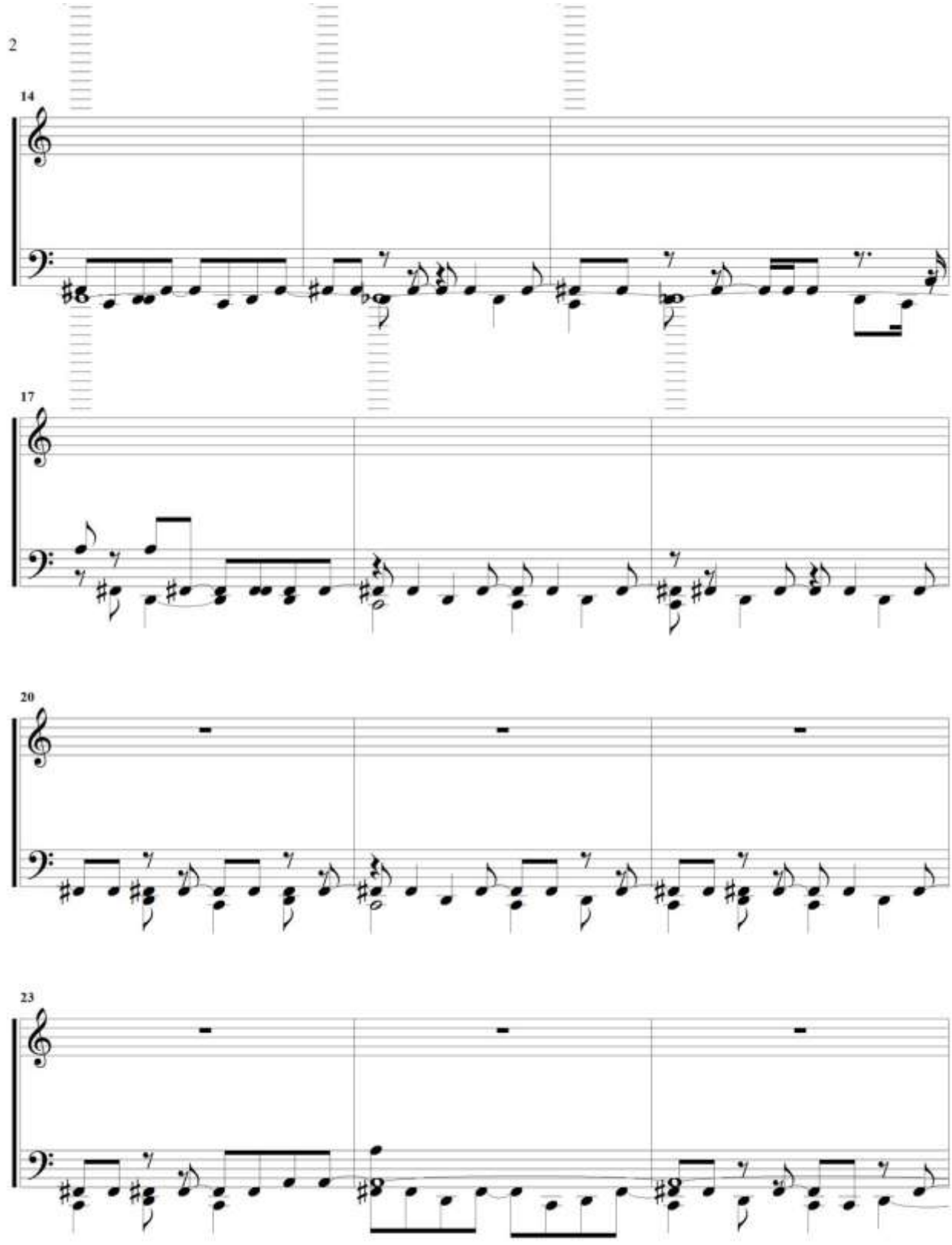
Pitch Byte (Dec)	Bunyi	Pitch Byte (Dec)	Bunyi3
35	Bass Drum 2	59	Ride Cymbal 2
36	Bass Drum 1	60	High Bongo
37	Side Stick	61	Low Bongo
38	Snare Drum 1	62	Mute High Conga
39	Hand Clap	63	Open High Conga
40	Snare Drum 1	64	Low Conga
41	Low Tom 2	65	High Timbale
42	Closed Hi-hat	66	Low Tombale
43	Low Tom 1	67	High Agogo
44	Pedal Hi-hat	68	Low Agogo
45	Mid Tom 2	69	Cabasa
46	Open Hi-hat	70	Maracas
47	Mid Tom 1	71	Short Whistle
48	High Tom 2	72	Long Whistle
49	Crash Cymbal 1	73	Short Guiro
50	High Tom 1	74	Long Guiro
51	Ride Cymbal 1	75	Claves
52	Chinese Cymbal	76	High Wood Block
53	Ride Bell	77	Low Wood Block
54	Tambourine	78	Mute Cuica
55	Splash Cymbal	79	Open Cuica
56	Cowbell	80	Mute Triangle
57	Crash Cymbal 2	81	Open Triangle

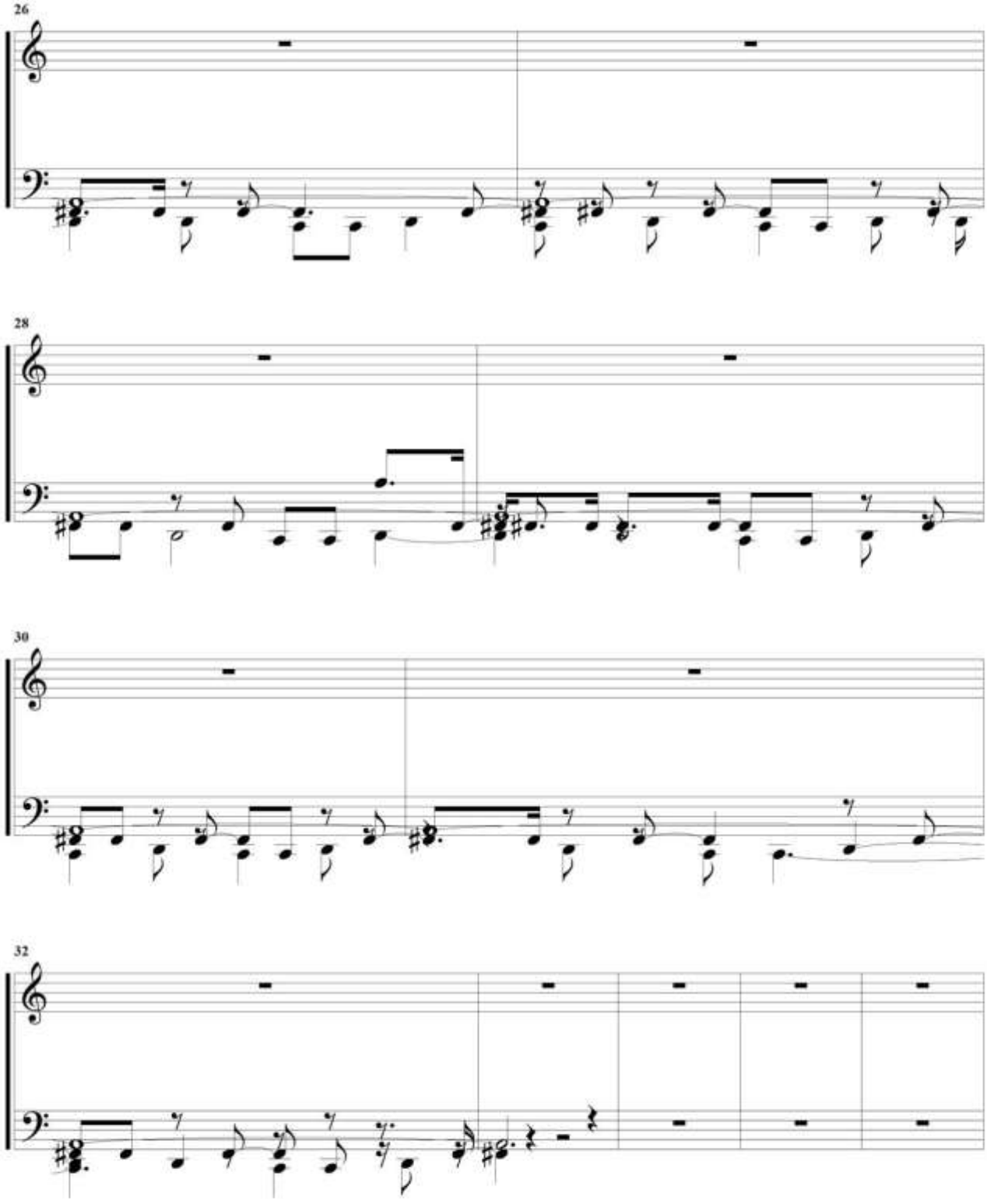
Lampiran E

Partitur Lagu Hasil Rekam Data MIDI

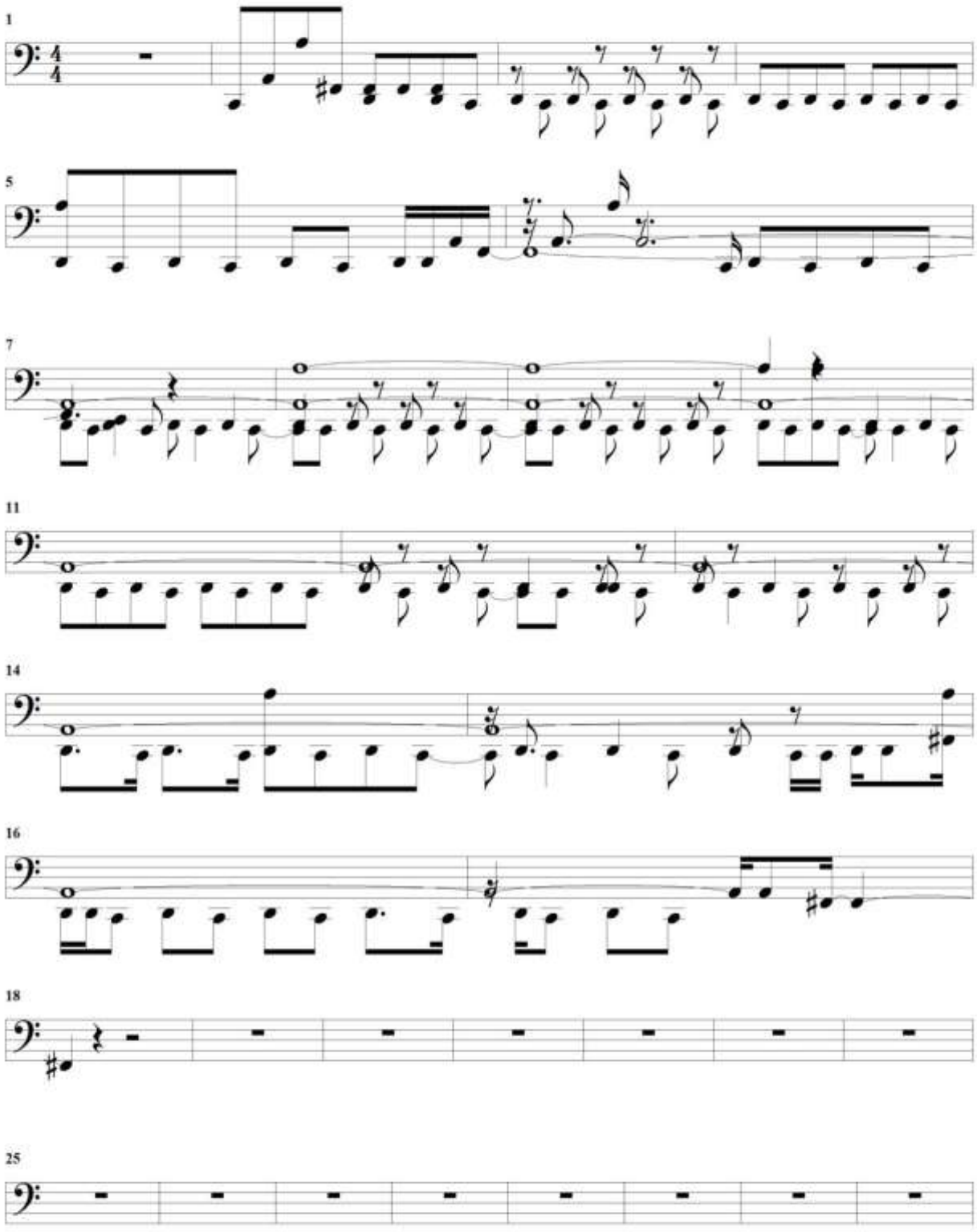
Allah Peduli



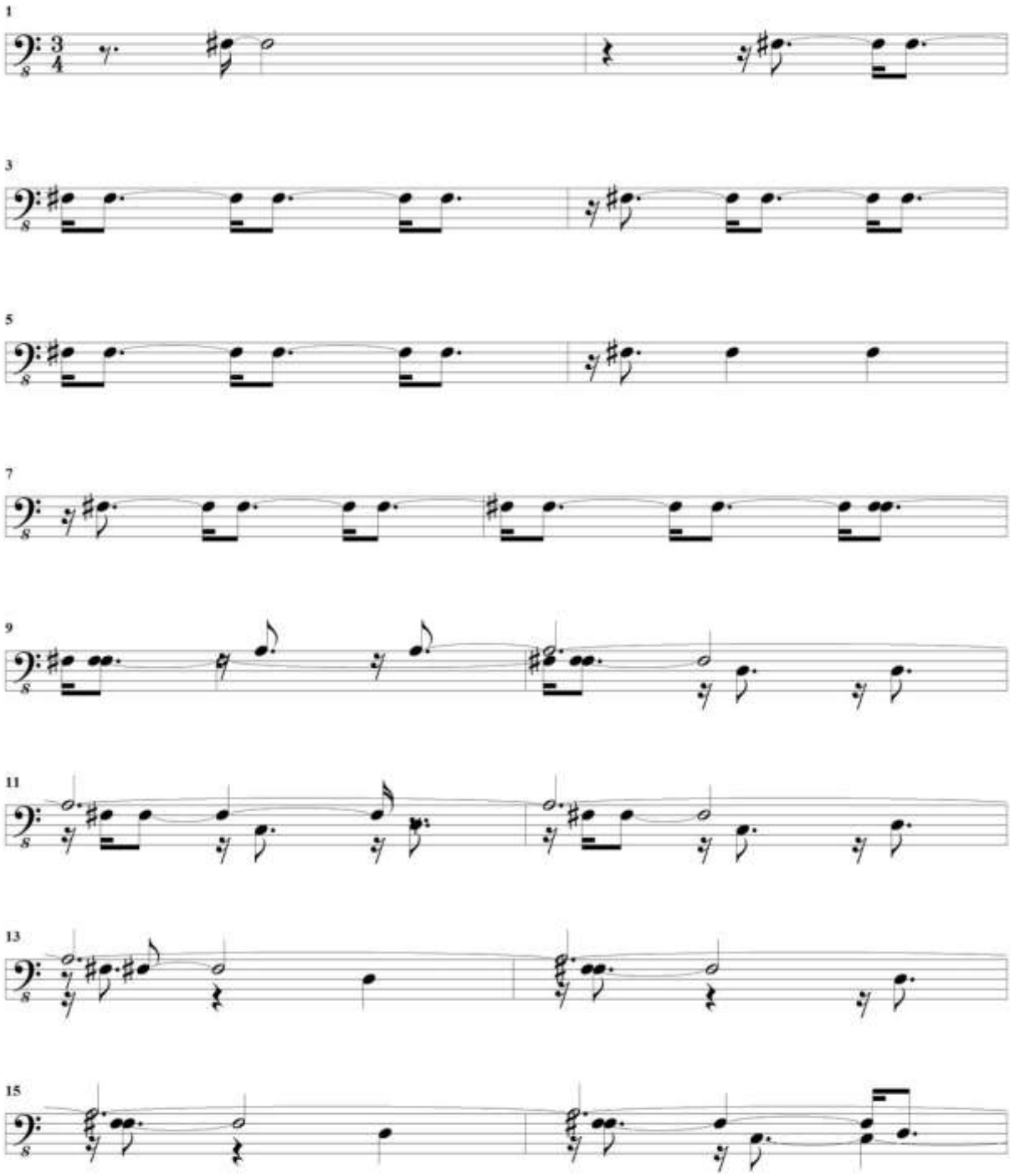

2
14
17
20
23

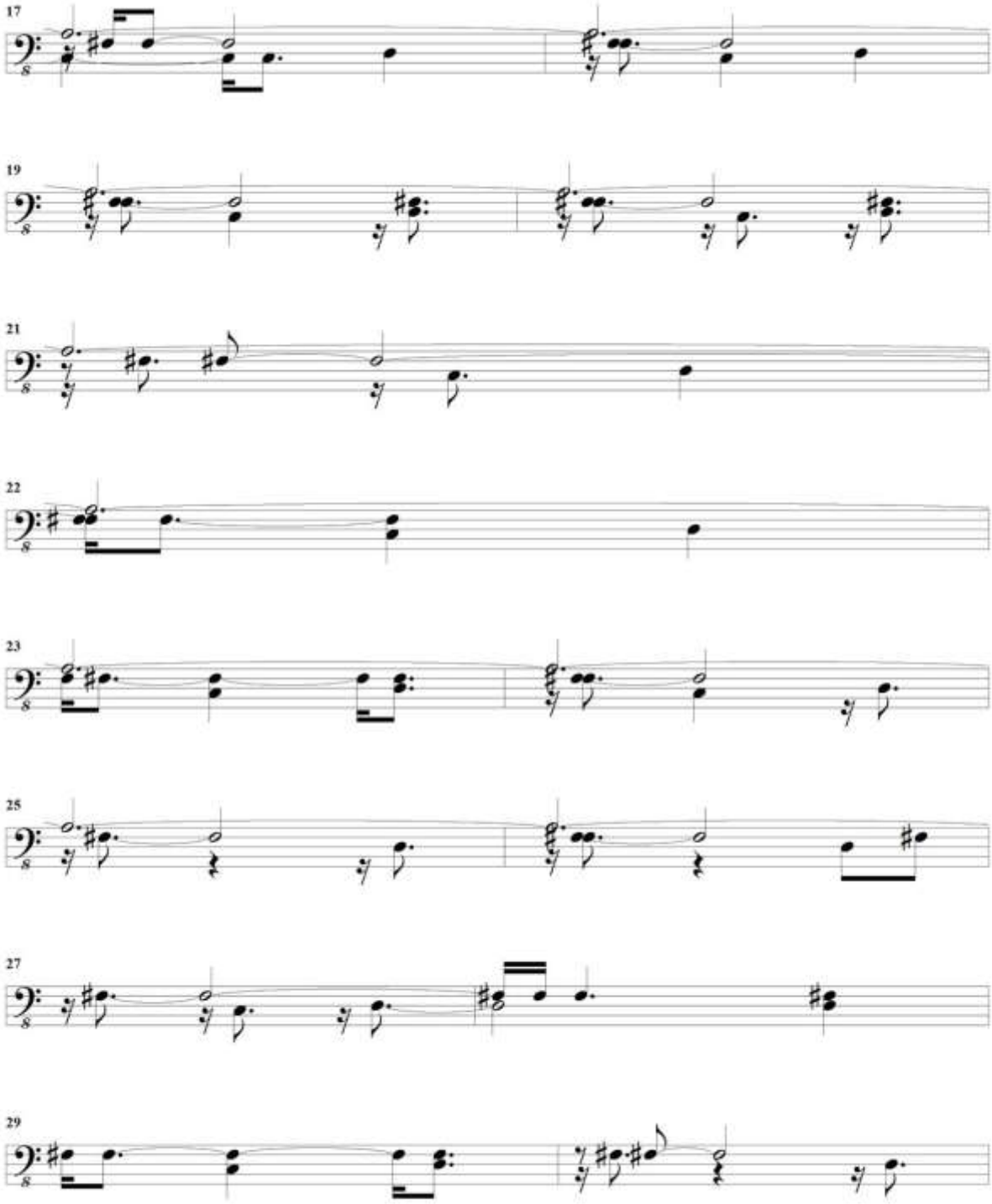

26
28
30
32

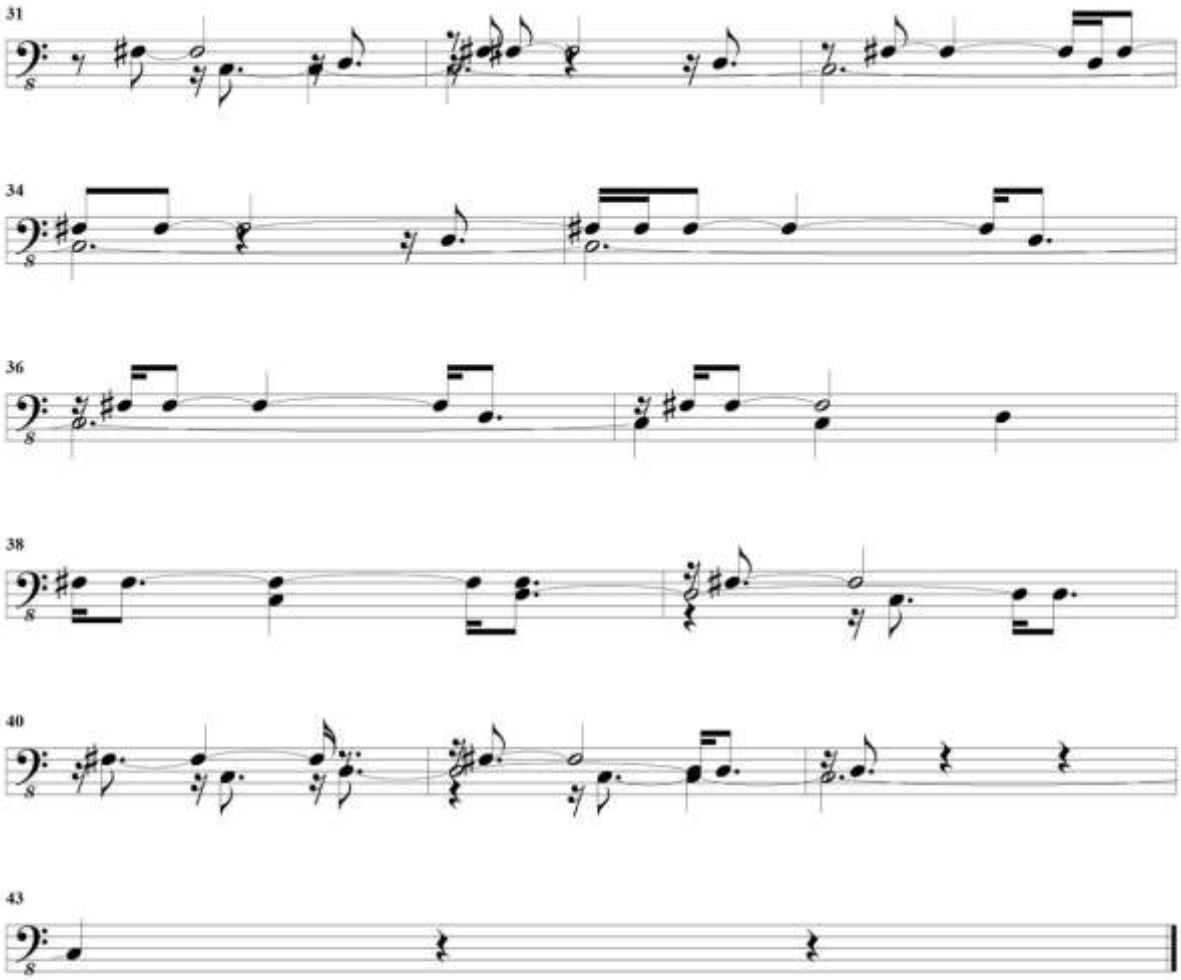
Sejak Yesus di Hatiku



O Amelia




17
19
21
22
23
25
27
29


31
34
36
38
40
43

Lampiran F

Datasheet Spesifikasi Umum ATMega 16

Features

- High-performance, Low-power Atmel® AVR® 8-bit Microcontroller
- Advanced RISC Architecture
  - 131 Powerful Instructions – Most Single-clock Cycle Execution
  - 32 x 8 General Purpose Working Registers
  - Fully Static Operation
  - Up to 16 MIPS Throughput at 16 MHz
  - On-chip 2-cycle Multiplier
- High Endurance Non-volatile Memory segments
  - 16 Kbytes of In-System Self-programmable Flash program memory
  - 512 Bytes EEPROM
  - 1 Kbyte Internal SRAM
  - Write/Erase Cycles: 10,000 Flash/100,000 EEPROM
  - Data retention: 20 years at 85°C/100 years at 25°C[1]
  - Optional Boot Code Section with Independent Lock Bits
    In-System Programming by On-chip Boot Program
    True Read-While-Write Operation
  - Programming Lock for Software Security
- JTAG (IEEE std. 1149.1 Compliant) Interface
  - Boundary-scan Capabilities According to the JTAG Standard
  - Extensive On-chip Debug Support
  - Programming of Flash, EEPROM, Fuses, and Lock Bits through the JTAG Interface
- Peripheral Features
  - Two 8-bit Timer/Counters with Separate Prescalers and Compare Modes
  - One 16-bit Timer/Counter with Separate Prescaler, Compare Mode, and Capture Mode
  - Real Time Counter with Separate Oscillator
  - Four PWM Channels
  - 8-channel, 10-bit ADC
    8 Single-ended Channels
    7 Differential Channels in TQFP Package Only
    2 Differential Channels with Programmable Gain at 1x, 10x, or 200x
  - Byte-oriented Two-wire Serial Interface
  - Programmable Serial USART
  - Master/Slave SPI Serial Interface
  - Programmable Watchdog Timer with Separate On-chip Oscillator
  - On-chip Analog Comparator
- Special Microcontroller Features
  - Power-on Reset and Programmable Brown-out Detection
  - Internal Calibrated RC Oscillator
  - External and Internal Interrupt Sources
  - Six Sleep Modes: Idle, ADC Noise Reduction, Power-save, Power-down, Standby and Extended Standby
- I/O and Packages
  - 32 Programmable I/O Lines
  - 40-pin PDIP, 44-lead TQFP, and 44-pad QFN/MLF
- Operating Voltages
  - 2.7V - 5.5V for ATmega16L
  - 4.5V - 5.5V for ATmega16
- Speed Grades
  - 0 - 8 MHz for ATmega16L
  - 0 - 16 MHz for ATmega16
- Power Consumption @ 1 MHz, 3V, and 25°C for ATmega16L
  - Active: 1.1 mA
  - Idle Mode: 0.35 mA
  - Power-down Mode: < 1 µA

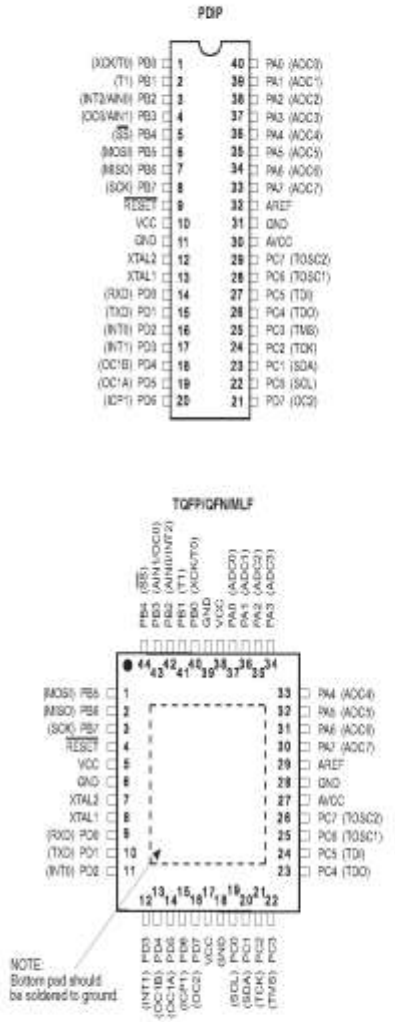
8-bit AVR® Microcontroller with 16K Bytes In-System Programmable Flash

ATmega16
ATmega16L

Rev. 2466T–AVR–07/10

Pin Configurations

Figure 1. Pinout ATmega16



Disclaimer

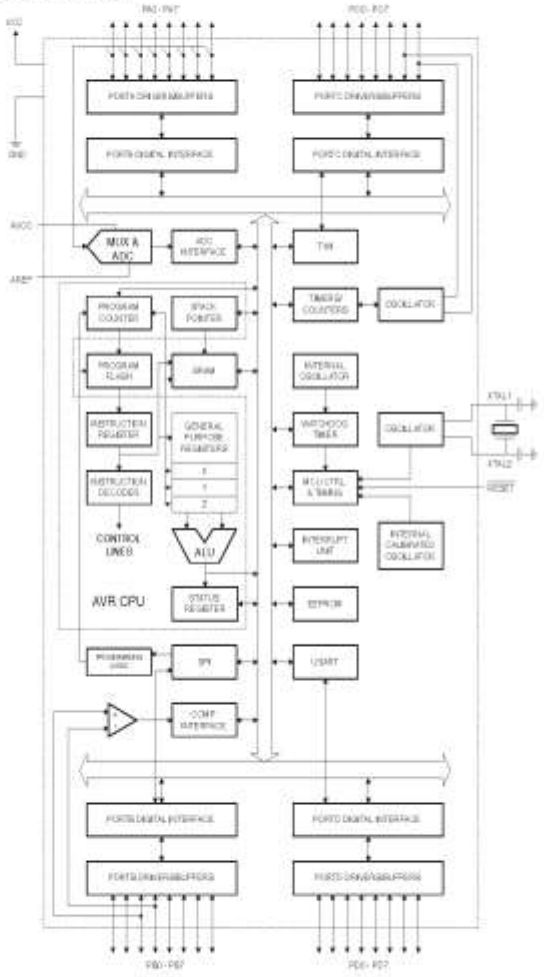
Typical values contained in this datasheet are based on simulations and characterization of other AVR microcontrollers manufactured on the same process technology. Min and Max values will be available after the device is characterized.

Overview

The ATmega16 is a low-power CMOS 8-bit microcontroller based on the AVR enhanced RISC architecture. By executing powerful instructions in a single clock cycle, the ATmega16 achieves throughputs approaching 1 MIPS per MHz allowing the system designer to optimize power consumption versus processing speed.

Block Diagram

Figure 2. Block Diagram



The AVR core combines a rich instruction set with 32 general purpose working registers. All the 32 registers are directly connected to the Arithmetic Logic Unit (ALU), allowing two independent registers to be accessed in one single instruction executed in one clock cycle. The resulting architecture is more code efficient while achieving throughputs up to ten times faster than conventional CISC microcontrollers.

The ATmega16 provides the following features: 16 Kbytes of In-System Programmable Flash Program memory with Read-While-Write capabilities, 512 bytes EEPROM, 1 Kbyte SRAM, 32 general purpose I/O lines, 32 general purpose working registers, a JTAG interface for Boundary-scan, On-chip Debugging support and programming, three flexible Timer/Counters with compare modes, Internal and External Interrupts, a serial programmable USART, a byte oriented Two-wire Serial Interface, an 8-channel, 10-bit ADC with optional differential input stage with programmable gain (TQFP package only), a programmable Watchdog Timer with Internal Oscillator, an SPI serial port, and six software selectable power saving modes. The Idle mode stops the CPU while allowing the USART, Two-wire interface, A/D Converter, SRAM, Timer/Counters, SPI port, and interrupt system to continue functioning. The Power-down mode saves the register contents but freezes the Oscillator, disabling all other chip functions until the next External Interrupt or Hardware Reset. In Power-save mode, the Asynchronous Timer continues to run, allowing the user to maintain a timer base while the rest of the device is sleeping. The ADC Noise Reduction mode stops the CPU and all I/O modules except Asynchronous Timer and ADC, to minimize switching noise during ADC conversions. In Standby mode, the crystal/resonator Oscillator is running while the rest of the device is sleeping. This allows very fast start-up combined with low-power consumption. In Extended Standby mode, both the main Oscillator and the Asynchronous Timer continue to run.

The device is manufactured using Atmel's high density nonvolatile memory technology. The On-chip ISP Flash allows the program memory to be reprogrammed in-system through an SPI serial interface, by a conventional nonvolatile memory programmer, or by an On-chip Boot program running on the AVR core. The boot program can use any interface to download the application program in the Application Flash memory. Software in the Boot Flash section will continue to run while the Application Flash section is updated, providing true Read-While-Write operation. By combining an 8-bit RISC CPU with In-System Self-Programmable Flash on a monolithic chip, the Atmel ATmega16 is a powerful microcontroller that provides a highly-flexible and cost-effective solution to many embedded control applications.

The ATmega16 AVR is supported with a full suite of program and system development tools including: C compilers, macro assemblers, program debugger/simulators, in-circuit emulators, and evaluation kits.

Pin Descriptions

VCC Digital supply voltage.

GND Ground.

Port A (PA7..PA0) Port A serves as the analog inputs to the A/D Converter.

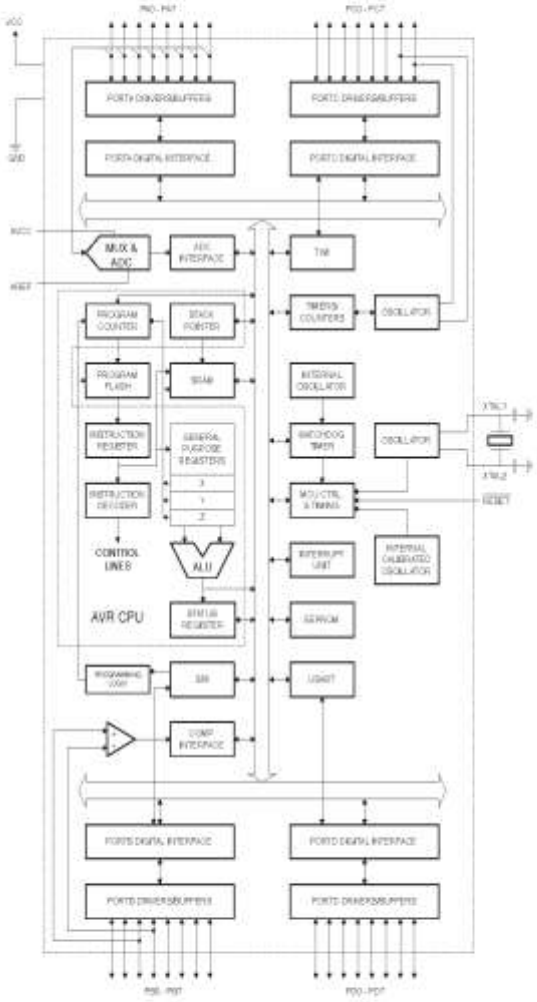
Port A also serves as an 8-bit bi-directional I/O port, if the A/D Converter is not used. Port pins can provide internal pull-up resistors (selected for each bit). The Port A output buffers have symmetrical drive characteristics with both high sink and source capability. When pins PA0 to PA7 are used as inputs and are externally pulled low, they will source current if the internal pull-up resistors are activated. The Port A pins are tri-stated when a reset condition becomes active, even if the clock is not running.

Overview

The ATmega16 is a low-power CMOS 8-bit microcontroller based on the AVR enhanced RISC architecture. By executing powerful instructions in a single clock cycle, the ATmega16 achieves throughputs approaching 1 MIPS per MHz allowing the system designer to optimize power consumption versus processing speed.

Block Diagram

Figure 2. Block Diagram



The AVR core combines a rich instruction set with 32 general purpose working registers. All the 32 registers are directly connected to the Arithmetic Logic Unit (ALU), allowing two independent registers to be accessed in one single instruction executed in one clock cycle. The resulting architecture is more code efficient while achieving throughputs up to ten times faster than conventional CISC microcontrollers.

The ATmega16 provides the following features: 16 Kbytes of In-System Programmable Flash Program memory with Read-While-Write capabilities, 512 bytes EEPROM, 1 Kbyte SRAM, 32 general purpose I/O lines, 32 general purpose working registers, a JTAG interface for Boundary-scan, On-chip Debugging support and programming, three flexible Timer/Counters with compare modes, Internal and External Interrupts, a serial programmable USART, a byte oriented Two-wire Serial Interface, an 8-channel, 10-bit ADC with optional differential input stage with programmable gain (TQFP package only), a programmable Watchdog Timer with Internal Oscillator, an SPI serial port, and six software selectable power saving modes. The Idle mode stops the CPU while allowing the USART, Two-wire interface, A/D Converter, SRAM, Timer/Counters, SPI port, and interrupt system to continue functioning. The Power-down mode saves the register contents but freezes the Oscillator, disabling all other chip functions until the next External Interrupt or Hardware Reset. In Power-save mode, the Asynchronous Timer continues to run, allowing the user to maintain a timer base while the rest of the device is sleeping. The ADC Noise Reduction mode stops the CPU and all I/O modules except Asynchronous Timer and ADC, to minimize switching noise during ADC conversions. In Standby mode, the crystal/resonator Oscillator is running while the rest of the device is sleeping. This allows very fast start-up combined with low-power consumption. In Extended Standby mode, both the main Oscillator and the Asynchronous Timer continue to run.

The device is manufactured using Atmel's high density nonvolatile memory technology. The On-chip ISP Flash allows the program memory to be reprogrammed in-system through an SPI serial interface, by a conventional nonvolatile memory programmer, or by an On-chip Boot program running on the AVR core. The boot program can use any interface to download the application program in the Application Flash memory. Software in the Boot Flash section will continue to run while the Application Flash section is updated, providing true Read-While-Write operation. By combining an 8-bit RISC CPU with In-System Self-Programmable Flash on a monolithic chip, the Atmel ATmega16 is a powerful microcontroller that provides a highly-flexible and cost-effective solution to many embedded control applications.

The ATmega16 AVR is supported with a full suite of program and system development tools including: C compilers, macro assemblers, program debugger/simulators, in-circuit emulators, and evaluation kits.

Pin Descriptions

VCC Digital supply voltage.

GND Ground.

Port A (PA7..PA0) Port A serves as the analog inputs to the A/D Converter.

Port A also serves as an 8-bit bi-directional I/O port, if the A/D Converter is not used. Port pins can provide internal pull-up resistors (selected for each bit). The Port A output buffers have symmetrical drive characteristics with both high sink and source capability. When pins PA0 to PA7 are used as inputs and are externally pulled low, they will source current if the internal pull-up resistors are activated. The Port A pins are tri-stated when a reset condition becomes active, even if the clock is not running.

Lampiran G

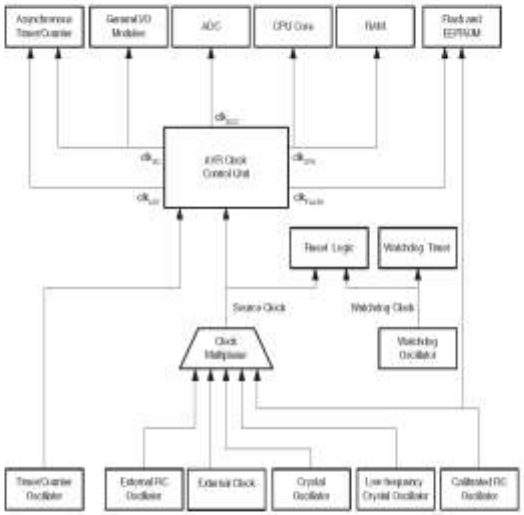
Datasheet Penggunaan Clock Eksternal pada ATMega 16

System Clock and Clock Options

Clock Systems and their Distribution

Figure 11 presents the principal clock systems in the AVR and their distribution. All of the clocks need not be active at a given time. In order to reduce power consumption, the clocks to modules not being used can be halted by using different sleep modes, as described in "Power Management and Sleep Modes" on page 32. The clock systems are detailed Figure 11.

Figure 11. Clock Distribution



CPU Clock – clk_{CPU}

The CPU clock is routed to parts of the system concerned with operation of the AVR core. Examples of such modules are the General Purpose Register File, the Status Register and the data memory holding the Stack Pointer. Halting the CPU clock inhibits the core from performing general operations and calculations.

I/O Clock – $clk_{I/O}$

The I/O clock is used by the majority of the I/O modules, like Timer/Counters, SPI, and USART. The I/O clock is also used by the External Interrupt module, but note that some external interrupts are detected by asynchronous logic, allowing such interrupts to be detected even if the I/O clock is halted. Also note that address recognition in the TWI module is carried out asynchronously when $clk_{I/O}$ is halted, enabling TWI address reception in all sleep modes.

Flash Clock – clk_{FLASH}

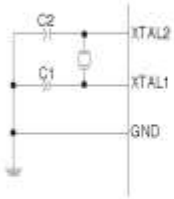
The Flash clock controls operation of the Flash interface. The Flash clock is usually active simultaneously with the CPU clock.

Asynchronous Timer Clock – clk_{ASY}

The Asynchronous Timer clock allows the Asynchronous Timer/Counter to be clocked directly from an external 32 kHz clock crystal. The dedicated clock domain allows using this Timer/Counter as a real-time counter even when the device is in sleep mode.

choosing capacitors for use with crystals are given in Table 4. For ceramic resonators, the capacitor values given by the manufacturer should be used.

Figure 12. Crystal Oscillator Connections



The Oscillator can operate in three different modes, each optimized for a specific frequency range. The operating mode is selected by the fuses CKSEL3..1 as shown in Table 4.

Table 4. Crystal Oscillator Operating Modes

CKOPT	CKSEL3..1	Frequency Range (MHz)	Recommended Range for Capacitors C1 and C2 for Use with Crystals (pF)
1	101[1]	0.4 - 0.9	–
1	110	0.9 - 3.0	12 - 22
1	111	3.0 - 8.0	12 - 22
0	101, 110, 111	1.0 ≤	12 - 22

Note: 1. This option should not be used with crystals, only with ceramic resonators.

G – 1

ADC Clock – clk_{ADC}

The ADC is provided with a dedicated clock domain. This allows halting the CPU and I/O clocks in order to reduce noise generated by digital circuitry. This gives more accurate ADC conversion results.

Clock Sources

The device has the following clock source options, selectable by Flash Fuse bits as shown below. The clock from the selected source is input to the AVR clock generator, and routed to the appropriate modules.

Table 2. Device Clocking Options Select[1]

Device Clocking Option	CKSEL3..0
External Crystal/Ceramic Resonator	1111 - 1010
External Low-frequency Crystal	1001
External RC Oscillator	1000 - 0101
Calibrated Internal RC Oscillator	0100 - 0001
External Clock	0000

Note: 1. For all fuses "1" means unprogrammed while "0" means programmed.

The various choices for each clocking option is given in the following sections. When the CPU wakes up from Power-down or Power-save, the selected clock source is used to time the start-up, ensuring stable Oscillator operation before instruction execution starts. When the CPU starts from Reset, there is as an additional delay allowing the power to reach a stable level before commencing normal operation. The Watchdog Oscillator is used for timing this real-time part of the start-up time. The number of WDT Oscillator cycles used for each time-out is shown in Table 3. The frequency of the Watchdog Oscillator is voltage dependent as shown in "ATmega16 Typical Characteristics" on page 299

Table 3. Number of Watchdog Oscillator Cycles

Typ Time-out (V_{CC} = 5.0V)	Typ Time-out (V_{CC} = 3.0V)	Number of Cycles
4.1 ms	4.3 ms	4K (4,096)
65 ms	69 ms	64K (65,536)

Default Clock Source

The device is shipped with CKSEL = "0001" and SUT = "10". The default clock source setting is therefore the 1 MHz Internal RC Oscillator with longest startup time. This default setting ensures that all users can make their desired clock source setting using an In-System or Parallel Programmer.

Crystal Oscillator

XTAL1 and XTAL2 are input and output, respectively, of an inverting amplifier which can be configured for use as an On-chip Oscillator, as shown in Figure 12. Either a quartz crystal or a ceramic resonator may be used. The CKOPT Fuse selects between two different Oscillator amplifier modes. When CKOPT is programmed, the Oscillator output will oscillate will a full rail-to-rail swing on the output. This mode is suitable when operating in a very noisy environment or when the output from XTAL2 drives a second clock buffer. This mode has a wide frequency range. When CKOPT is unprogrammed, the Oscillator has a smaller output swing. This reduces power consumption considerably. This mode has a limited frequency range and it can not be used to drive other clock buffers.

For resonators, the maximum frequency is 8 MHz with CKOPT unprogrammed and 16 MHz with CKOPT programmed. C1 and C2 should always be equal for both crystals and resonators. The optimal value of the capacitors depends on the crystal or resonator in use, the amount of stray capacitance, and the electromagnetic noise of the environment. Some initial guidelines for

Lampiran H

Tabel Crystall Clock untuk ATMega 16

- **Bit 11:0 – UBRR11:0: USART Baud Rate Register**

This is a 12-bit register which contains the USART baud rate. The UBRRH contains the four most significant bits, and the UBRRL contains the 8 least significant bits of the USART baud rate. Ongoing transmissions by the transmitter and receiver will be corrupted if the baud rate is changed. Writing UBRRL will trigger an immediate update of the baud rate prescaler.

Examples of Baud Rate Setting

For standard crystal and resonator frequencies, the most commonly used baud rates for asynchronous operation can be generated by using the UBRR settings in Table 68. UBRR values which yield an actual baud rate differing less than 0.5% from the target baud rate, are bold in the table. Higher error ratings are acceptable, but the receiver will have less noise resistance when the error ratings are high, especially for large serial frames (see "Asynchronous Operational Range" on page 159). The error values are calculated using the following equation:

$$\text{Error}[\%] = \left(\frac{\text{BaudRate}_{\text{Closest Match}}}{\text{BaudRate}} - 1\right) \cdot 100\%$$

Table 68. Examples of UBRR Settings for Commonly Used Oscillator Frequencies

Baud Rate (bps)	f_{osc} = 1.0000 MHz				f_{osc} = 1.8432 MHz				f_{osc} = 2.0000 MHz			
	U2X = 0		U2X = 1		U2X = 0		U2X = 1		U2X = 0		U2X = 1	
	UBRR	Error	UBRR	Error	UBRR	Error	UBRR	Error	UBRR	Error	UBRR	Error
2400	25	0.2%	51	0.2%	47	0.0%	95	0.0%	51	0.2%	103	0.2%
4800	12	0.2%	25	0.2%	23	0.0%	47	0.0%	25	0.2%	51	0.2%
9600	6	-7.0%	12	0.2%	11	0.0%	23	0.0%	12	0.2%	25	0.2%
14.4k	3	8.5%	8	-3.5%	7	0.0%	15	0.0%	8	-3.5%	16	2.1%
19.2k	2	8.5%	6	-7.0%	5	0.0%	11	0.0%	6	-7.0%	12	0.2%
28.8k	1	8.5%	3	8.5%	3	0.0%	7	0.0%	3	8.5%	8	-3.5%
38.4k	1	-18.6%	2	8.5%	2	0.0%	5	0.0%	2	8.5%	6	-7.0%
57.6k	0	8.5%	1	8.5%	1	0.0%	3	0.0%	1	8.5%	3	8.5%
76.8k	–	–	1	-18.6%	1	-25.0%	2	0.0%	1	-18.6%	2	8.5%
115.2k	–	–	0	8.5%	0	0.0%	1	0.0%	0	8.5%	1	8.5%
230.4k	–	–	–	–	–	–	0	0.0%	–	–	–	–
250k	–	–	–	–	–	–	–	–	–	–	0	0.0%
Max (1)	62.5 Kbps		125 Kbps		115.2 Kbps		230.4 Kbps		125 Kbps		250 Kbps	

1. UBRR = 0, Error = 0.0%

Table 69. Examples of UBRR Settings for Commonly Used Oscillator Frequencies (Continued)

Baud Rate (bps)	f_{osc} = 3.6864 MHz				f_{osc} = 4.0000 MHz				f_{osc} = 7.3728 MHz			
	U2X = 0		U2X = 1		U2X = 0		U2X = 1		U2X = 0		U2X = 1	
	UBRR	Error	UBRR	Error	UBRR	Error	UBRR	Error	UBRR	Error	UBRR	Error
2400	95	0.0%	191	0.0%	103	0.2%	207	0.2%	191	0.0%	383	0.0%
4800	47	0.0%	95	0.0%	51	0.2%	103	0.2%	95	0.0%	191	0.0%
9600	23	0.0%	47	0.0%	25	0.2%	51	0.2%	47	0.0%	95	0.0%
14.4k	15	0.0%	31	0.0%	16	2.1%	34	-0.8%	31	0.0%	63	0.0%
19.2k	11	0.0%	23	0.0%	12	0.2%	25	0.2%	23	0.0%	47	0.0%
28.8k	7	0.0%	15	0.0%	8	-3.5%	16	2.1%	15	0.0%	31	0.0%
38.4k	5	0.0%	11	0.0%	6	-7.0%	12	0.2%	11	0.0%	23	0.0%
57.6k	3	0.0%	7	0.0%	3	8.5%	8	-3.5%	7	0.0%	15	0.0%
76.8k	2	0.0%	5	0.0%	2	8.5%	6	-7.0%	5	0.0%	11	0.0%
115.2k	1	0.0%	3	0.0%	1	8.5%	3	8.5%	3	0.0%	7	0.0%
230.4k	0	0.0%	1	0.0%	0	8.5%	1	8.5%	1	0.0%	3	0.0%
250k	0	-7.8%	1	-7.8%	0	0.0%	1	0.0%	1	-7.8%	3	-7.8%
0.5M	–	–	0	-7.8%	–	–	0	0.0%	0	-7.8%	1	-7.8%
1M	–	–	–	–	–	–	–	–	–	–	0	-7.8%
Max (1)	230.4 Kbps		460.8 Kbps		250 Kbps		0.5 Mbps		460.8 Kbps		921.6 Kbps	

1. UBRR = 0, Error = 0.0%

Table 70. Examples of UBRR Settings for Commonly Used Oscillator Frequencies (Continued)

Baud Rate (bps)	f_{osc} = 8.0000 MHz				f_{osc} = 11.0592 MHz				f_{osc} = 14.7456 MHz			
	U2X = 0		U2X = 1		U2X = 0		U2X = 1		U2X = 0		U2X = 1	
	UBRR	Error	UBRR	Error	UBRR	Error	UBRR	Error	UBRR	Error	UBRR	Error
2400	207	0.2%	416	-0.1%	287	0.0%	575	0.0%	383	0.0%	767	0.0%
4800	103	0.2%	207	0.2%	143	0.0%	287	0.0%	191	0.0%	383	0.0%
9600	51	0.2%	103	0.2%	71	0.0%	143	0.0%	95	0.0%	191	0.0%
14.4k	34	-0.8%	68	0.6%	47	0.0%	95	0.0%	63	0.0%	127	0.0%
19.2k	25	0.2%	51	0.2%	35	0.0%	71	0.0%	47	0.0%	95	0.0%
28.8k	16	2.1%	34	-0.8%	23	0.0%	47	0.0%	31	0.0%	63	0.0%
38.4k	12	0.2%	25	0.2%	17	0.0%	35	0.0%	23	0.0%	47	0.0%
57.6k	8	-3.5%	16	2.1%	11	0.0%	23	0.0%	15	0.0%	31	0.0%
76.8k	6	-7.0%	12	0.2%	8	0.0%	17	0.0%	11	0.0%	23	0.0%
115.2k	3	8.5%	8	-3.5%	5	0.0%	11	0.0%	7	0.0%	15	0.0%
230.4k	1	8.5%	3	8.5%	2	0.0%	5	0.0%	3	0.0%	7	0.0%
250k	1	0.0%	3	0.0%	2	-7.8%	5	-7.8%	3	-7.8%	6	5.3%
0.5M	0	0.0%	1	0.0%	–	–	2	-7.8%	1	-7.8%	3	-7.8%
1M	–	–	0	0.0%	–	–	–	–	0	-7.8%	1	-7.8%
Max (1)	0.5 Mbps		1 Mbps		691.2 Kbps		1.3824 Mbps		921.6 Kbps		1.8432 Mbps	

1. UBRR = 0, Error = 0.0%

Table 71. Examples of UBRR Settings for Commonly Used Oscillator Frequencies (Continued)

Baud Rate (bps)	f_{osc} = 16.0000 MHz				f_{osc} = 18.4320 MHz				f_{osc} = 20.0000 MHz			
	U2X = 0		U2X = 1		U2X = 0		U2X = 1		U2X = 0		U2X = 1	
	UBRR	Error	UBRR	Error	UBRR	Error	UBRR	Error	UBRR	Error	UBRR	Error
2400	416	-0.1%	832	0.0%	479	0.0%	959	0.0%	520	0.0%	1041	0.0%
4800	207	0.2%	416	-0.1%	239	0.0%	479	0.0%	259	0.2%	520	0.0%
9600	103	0.2%	207	0.2%	119	0.0%	239	0.0%	129	0.2%	259	0.2%
14.4k	68	0.6%	138	-0.1%	79	0.0%	159	0.0%	86	-0.2%	173	-0.2%
19.2k	51	0.2%	103	0.2%	59	0.0%	119	0.0%	64	0.2%	129	0.2%
28.8k	34	-0.8%	68	0.6%	39	0.0%	79	0.0%	42	0.9%	86	-0.2%
38.4k	25	0.2%	51	0.2%	29	0.0%	59	0.0%	32	-1.4%	64	0.2%
57.6k	16	2.1%	34	-0.8%	19	0.0%	39	0.0%	21	-1.4%	42	0.9%
76.8k	12	0.2%	25	0.2%	14	0.0%	29	0.0%	15	1.7%	32	-1.4%
115.2k	8	-3.5%	16	2.1%	9	0.0%	19	0.0%	10	-1.4%	21	-1.4%
230.4k	3	8.5%	8	-3.5%	4	0.0%	9	0.0%	4	8.5%	10	-1.4%
250k	3	0.0%	7	0.0%	4	-7.8%	8	2.4%	4	0.0%	9	0.0%
0.5M	1	0.0%	3	0.0%	–	–	4	-7.8%	–	–	4	0.0%
1M	0	0.0%	1	0.0%	–	–	–	–	–	–	–	–
Max (1)	1 Mbps		2 Mbps		1.152 Mbps		2.304 Mbps		1.25 Mbps		2.5 Mbps	

1. UBRR = 0, Error = 0.0%

Lampiran I

Datasheet ADC pada ATMega 16

Analog to Digital Converter

Features

- 10-bit Resolution
- 0.5 LSB Integral Non-linearity
- ±2 LSB Absolute Accuracy
- 13 µs- 260 µs Conversion Time
- Up to 15 kSPS at Maximum Resolution
- 8 Multiplexed Single Ended Input Channels
- 7 Differential Input Channels
- 2 Differential Input Channels with Optional Gain of 10x and 200x
- Optional Left adjustment for ADC Result Readout
- 0 - V_{CC} ADC Input Voltage Range
- Selectable 2.56V ADC Reference Voltage
- Free Running or Single Conversion Mode
- ADC Start Conversion by Auto Triggering on Interrupt Sources
- Interrupt on ADC Conversion Complete
- Sleep Mode Noise Canceler

The ATmega16 features a 10-bit successive approximation ADC. The ADC is connected to an 8-channel Analog Multiplexer which allows 8 single-ended voltage inputs constructed from the pins of Port A. The single-ended voltage inputs refer to 0V (GND).

The device also supports 16 differential voltage input combinations. Two of the differential inputs (ADC1, ADC0 and ADC3, ADC2) are equipped with a programmable gain stage, providing amplification steps of 0 dB (1x), 20 dB (10x), or 46 dB (200x) on the differential input voltage before the A/D conversion. Seven differential analog input channels share a common negative terminal (ADC1), while any other ADC input can be selected as the positive input terminal. If 1x or 10x gain is used, 8-bit resolution can be expected. If 200x gain is used, 7-bit resolution can be expected.

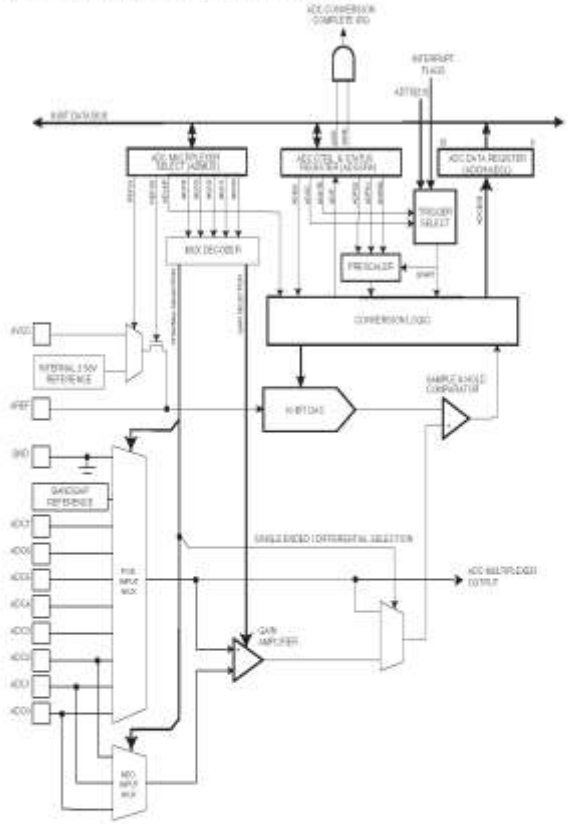
The ADC contains a Sample and Hold circuit which ensures that the input voltage to the ADC is held at a constant level during conversion. A block diagram of the ADC is shown in Figure 98.

The ADC has a separate analog supply voltage pin, AVCC. AVCC must not differ more than ±0.3V from V_{CC}. See the paragraph "ADC Noise Canceler" on page 211 on how to connect this pin.

Internal reference voltages of nominally 2.56V or AVCC are provided On-chip. The voltage reference may be externally decoupled at the AREF pin by a capacitor for better noise performance.

ATmega16(L)

Figure 98. Analog to Digital Converter Block Schematic



Operation

The ADC converts an analog input voltage to a 10-bit digital value through successive approximation. The minimum value represents GND and the maximum value represents the voltage on the AREF pin minus 1 LSB. Optionally, AVCC or an internal 2.56V reference voltage may be connected to the AREF pin by writing to the REFSn bits in the ADMUX Register. The internal voltage reference may thus be decoupled by an external capacitor at the AREF pin to improve noise immunity.

The analog input channel and differential gain are selected by writing to the MUX bits in ADMUX. Any of the ADC input pins, as well as GND and a fixed bandgap voltage reference, can be selected as single ended inputs to the ADC. A selection of ADC input pins can be selected as positive and negative inputs to the differential gain amplifier.

If differential channels are selected, the differential gain stage amplifies the voltage difference between the selected input channel pair by the selected gain factor. This amplified value then

becomes the analog input to the ADC. If single ended channels are used, the gain amplifier is bypassed altogether.

The ADC is enabled by setting the ADC Enable bit, ADEN in ADCSRA. Voltage reference and input channel selections will not go into effect until ADEN is set. The ADC does not consume power when ADEN is cleared, so it is recommended to switch off the ADC before entering power saving sleep modes.

The ADC generates a 10-bit result which is presented in the ADC Data Registers, ADCH and ADCL. By default, the result is presented right adjusted, but can optionally be presented left adjusted by setting the ADLAR bit in ADMUX.

If the result is left adjusted and no more than 8-bit precision is required, it is sufficient to read ADCH. Otherwise, ADCL must be read first, then ADCH, to ensure that the content of the Data Registers belongs to the same conversion. Once ADCL is read, ADC access to Data Registers is blocked. This means that if ADCL has been read, and a conversion completes before ADCH is read, neither register is updated and the result from the conversion is lost. When ADCH is read, ADC access to the ADCH and ADCL Registers is re-enabled.

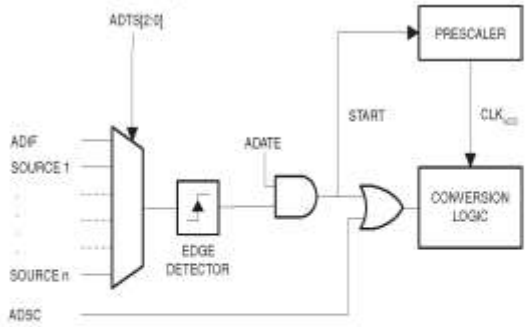
The ADC has its own interrupt which can be triggered when a conversion completes. When ADC access to the Data Registers is prohibited between reading of ADCH and ADCL, the interrupt will trigger even if the result is lost.

Starting a Conversion

A single conversion is started by writing a logical one to the ADC Start Conversion bit, ADSC. This bit stays high as long as the conversion is in progress and will be cleared by hardware when the conversion is completed. If a different data channel is selected while a conversion is in progress, the ADC will finish the current conversion before performing the channel change.

Alternatively, a conversion can be triggered automatically by various sources. Auto Triggering is enabled by setting the ADC Auto Trigger Enable bit, ADATE in ADCSRA. The trigger source is selected by setting the ADC Trigger Select bits, ADTS in SFIOR (see description of the ADTS bits for a list of the trigger sources). When a positive edge occurs on the selected trigger signal, the ADC prescaler is reset and a conversion is started. This provides a method of starting conversions at fixed intervals. If the trigger signal still is set when the conversion completes, a new conversion will not be started. If another positive edge occurs on the trigger signal during conversion, the edge will be ignored. Note that an Interrupt Flag will be set even if the specific interrupt is disabled or the global interrupt enable bit in SREG is cleared. A conversion can thus be triggered without causing an interrupt. However, the Interrupt Flag must be cleared in order to trigger a new conversion at the next interrupt event.

Figure 99. ADC Auto Trigger Logic

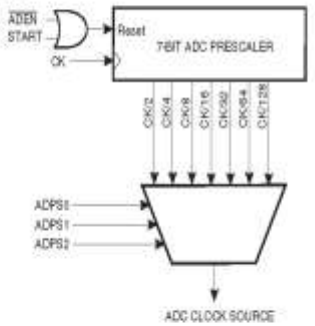


Using the ADC Interrupt Flag as a trigger source makes the ADC start a new conversion as soon as the ongoing conversion has finished. The ADC then operates in Free Running mode, constantly sampling and updating the ADC Data Register. The first conversion must be started by writing a logical one to the ADSC bit in ADCSRA. In this mode the ADC will perform successive conversions independently of whether the ADC Interrupt Flag, ADIF is cleared or not.

If Auto Triggering is enabled, single conversions can be started by writing ADSC in ADCSRA to one. ADSC can also be used to determine if a conversion is in progress. The ADSC bit will be read as one during a conversion, independently of how the conversion was started.

Prescaling and Conversion Timing

Figure 100. ADC Prescaler



By default, the successive approximation circuitry requires an input clock frequency between 50 kHz and 200 kHz to get maximum resolution. If a lower resolution than 10 bits is needed, the input clock frequency to the ADC can be higher than 200 kHz to get a higher sample rate.

The ADC module contains a prescaler, which generates an acceptable ADC clock frequency from any CPU frequency above 100 kHz. The prescaling is set by the ADPS bits in ADCSRA. The prescaler starts counting from the moment the ADC is switched on by setting the ADEN bit in ADCSRA. The prescaler keeps running for as long as the ADEN bit is set, and is continuously reset when ADEN is low.

When initiating a single ended conversion by setting the ADSC bit in ADCSRA, the conversion starts at the following rising edge of the ADC clock cycle. See "Differential Gain Channels" on page 209 for details on differential conversion timing.

A normal conversion takes 13 ADC clock cycles. The first conversion after the ADC is switched on (ADEN in ADCSRA is set) takes 25 ADC clock cycles in order to initialize the analog circuitry.

The actual sample-and-hold takes place 1.5 ADC clock cycles after the start of a normal conversion and 13.5 ADC clock cycles after the start of a first conversion. When a conversion is complete, the result is written to the ADC Data Registers, and ADIF is set. In single conversion mode, ADSC is cleared simultaneously. The software may then set ADSC again, and a new conversion will be initiated on the first rising ADC clock edge.

When Auto Triggering is used, the prescaler is reset when the trigger event occurs. This assures a fixed delay from the trigger event to the start of conversion. In this mode, the sample-and-hold takes place 2 ADC clock cycles after the rising edge on the trigger source signal. Three additional CPU clock cycles are used for synchronization logic. When using Differential mode, along with Auto triggering from a source other than the ADC Conversion Complete, each conversion

sleep modes and the user wants to perform differential conversions, the user is advised to switch the ADC off and on after waking up from sleep to prompt an extended conversion to get a valid result.

Analog Input Circuitry

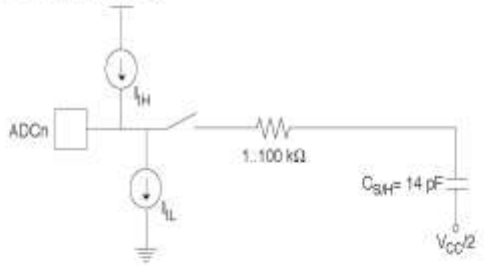
The Analog Input Circuitry for single ended channels is illustrated in Figure 105. An analog source applied to ADCn is subjected to the pin capacitance and input leakage of that pin, regardless of whether that channel is selected as input for the ADC. When the channel is selected, the source must drive the S/H capacitor through the series resistance (combined resistance in the input path).

The ADC is optimized for analog signals with an output impedance of approximately 10 kΩ or less. If such a source is used, the sampling time will be negligible. If a source with higher impedance is used, the sampling time will depend on how long time the source needs to charge the S/H capacitor, with can vary widely. The user is recommended to only use low impedant sources with slowly varying signals, since this minimizes the required charge transfer to the S/H capacitor.

If differential gain channels are used, the input circuitry looks somewhat different, although source impedances of a few hundred kΩ or less is recommended.

Signal components higher than the Nyquist frequency ($f_{ADC}/2$) should not be present for either kind of channels, to avoid distortion from unpredictable signal convolution. The user is advised to remove high frequency components with a low-pass filter before applying the signals as inputs to the ADC.

Figure 105. Analog Input Circuitry

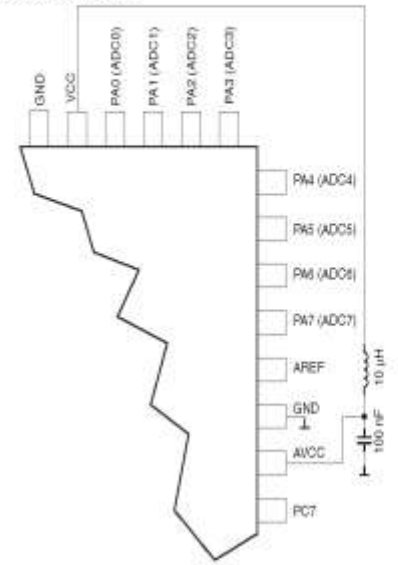


Analog Noise Canceling Techniques

Digital circuitry inside and outside the device generates EMI which might affect the accuracy of analog measurements. If conversion accuracy is critical, the noise level can be reduced by applying the following techniques:

1. Keep analog signal paths as short as possible. Keep them well away from high-speed switching digital tracks.
2. The AVCC pin on the device should be connected to the digital V_{CC} supply voltage via an LC network as shown in Figure 106.
3. Use the ADC noise canceler function to reduce induced noise from the CPU.
4. If any ADC port pins are used as digital outputs, it is essential that these do not switch while a conversion is in progress.

Figure 106. ADC Power Connections



Offset Compensation Schemes

The gain stage has a built-in offset cancellation circuitry that nulls the offset of differential measurements as much as possible. The remaining offset in the analog path can be measured directly by selecting the same channel for both differential inputs. This offset residue can be then subtracted in software from the measurement results. Using this kind of software based offset correction, offset on any channel can be reduced below one LSB.

ADC Accuracy Definitions

An n-bit single-ended ADC converts a voltage linearly between GND and V_{REF} in 2^n steps (LSBs). The lowest code is read as 0, and the highest code is read as 2^n-1.

Several parameters describe the deviation from the ideal behavior:

- Offset: The deviation of the first transition (0x000 to 0x001) compared to the ideal transition (at 0.5 LSB). Ideal value: 0 LSB.

Lampiran J
Datasheet IC MAX232

19-4323; Rev 11; 2/02

MAXIM

+5V-Powered, Multichannel RS-232 Drivers/Receivers

General Description

The MAX220–MAX249 family of line drivers/receivers is intended for all EIA/TIA-232E and V.28/V.24 communications interfaces, particularly applications where ±12V is not available.

These parts are especially useful in battery-powered systems, since their low-power shutdown mode reduces power dissipation to less than 5µW. The MAX225, MAX233, MAX235, and MAX245/MAX246/MAX247 use no external components and are recommended for applications where printed circuit board space is critical.

Applications

Portable Computers

Low-Power Modems

Interface Translation

Battery-Powered RS-232 Systems

Multidrop RS-232 Networks

Features

Superior to Bipolar

- **Operate from Single +5V Power Supply (+5V and +12V—MAX231/MAX239)**
- **Low-Power Receive Mode in Shutdown (MAX223/MAX242)**
- **Meet All EIA/TIA-232E and V.28 Specifications**
- **Multiple Drivers and Receivers**
- **3-State Driver and Receiver Outputs**
- **Open-Line Detection (MAX243)**

Ordering Information

PART	TEMP RANGE	PIN-PACKAGE
MAX220CPE	0°C to +70°C	16 Plastic DIP
MAX220CSE	0°C to +70°C	16 Narrow SO
MAX220CWE	0°C to +70°C	16 Wide SO
MAX220C/D	0°C to +70°C	Dice*
MAX220EPE	-40°C to +85°C	16 Plastic DIP
MAX220ESE	-40°C to +85°C	16 Narrow SO
MAX220EWE	-40°C to +85°C	16 Wide SO
MAX220EJE	-40°C to +85°C	16 CERDIP
MAX220MJE	-55°C to +125°C	16 CERDIP

Ordering Information continued at end of data sheet.

*Contact factory for dice specifications.

Selection Table

Part Number	Power Supply (V)	No. of RS-232 Drivers/Rx	No. of Ext. Caps	Nominal Cap. Value (µF)	SHDN & Three-State	Rx Active in SHDN	Data Rate (kbps)	Features
MAX220	+5	2/2	4	0.1	No	—	120	Ultra-low-power, industry-standard pinout
MAX222	+5	2/2	4	0.1	Yes	—	200	Low-power shutdown
MAX223 (MAX213)	+5	4/5	4	1.0 (0.1)	Yes	✔	120	MAX241 and receivers active in shutdown
MAX225	+5	5/5	0	—	Yes	✔	120	Available in SO
MAX230 (MAX200)	+5	5/0	4	1.0 (0.1)	Yes	—	120	5 drivers with shutdown
MAX231 (MAX201)	+5 and +7.5 to +13.2	2/2	2	1.0 (0.1)	No	—	120	Standard +5/+12V or battery supplies, same functions as MAX232
MAX232 (MAX202)	+5	2/2	4	1.0 (0.1)	No	—	120 (64)	Industry standard
MAX232A	+5	2/2	4	0.1	No	—	200	Higher slew rate, small caps
MAX233 (MAX203)	+5	2/2	0	—	No	—	120	No external caps
MAX233A	+5	2/2	0	—	No	—	200	No external caps, high slew rate
MAX234 (MAX204)	+5	4/0	4	1.0 (0.1)	No	—	120	Replaces 1488
MAX235 (MAX205)	+5	5/5	0	—	Yes	—	120	No external caps
MAX236 (MAX206)	+5	4/3	4	1.0 (0.1)	Yes	—	120	Shutdown, three state
MAX237 (MAX207)	+5	5/3	4	1.0 (0.1)	No	—	120	Complements IBM PC serial port
MAX238 (MAX208)	+5	4/4	4	1.0 (0.1)	No	—	120	Replaces 1488 and 1489
MAX239 (MAX209)	+5 and +7.5 to +13.2	3/5	2	1.0 (0.1)	No	—	120	Standard +5/+12V or battery supplies, single-package solution for IBM PC serial port
MAX240	+5	5/5	4	1.0	Yes	—	120	DIP or flatpack package
MAX241 (MAX211)	+5	4/5	4	1.0 (0.1)	Yes	—	120	Complete IBM PC serial port
MAX242	+5	2/2	4	0.1	Yes	✔	200	Separate shutdown and enable
MAX243	+5	2/2	4	0.1	No	—	200	Open-line detection simplifies cabling
MAX244	+5	8/10	4	1.0	No	—	120	High slew rate
MAX245	+5	8/10	0	—	Yes	✔✔	120	High slew rate, int. caps, two shutdown modes
MAX246	+5	8/10	0	—	Yes	✔✔	120	High slew rate, int. caps, three shutdown modes
MAX247	+5	8/9	0	—	Yes	✔✔	120	High slew rate, int. caps, nine operating modes
MAX248	+5	8/8	4	1.0	Yes	✔✔	120	High slew rate, selective half-chip enables
MAX249	+5	6/10	4	1.0	Yes	✔	120	Available in quad flat pack package

MAX220–MAX249

+5V-Powered, Multichannel RS-232 Drivers/Receivers

ABSOLUTE MAXIMUM RATINGS—MAX220/222/232A/233A/242/243

Supply Voltage (V_{CC}) ..... -0.3V to +6V

Input Voltages

T_{IN} ..... -0.3V to (V_{CC} + 0.3V)

R_{IN} (Except MAX220) ..... ±30V

R_{IN} (MAX220) ..... ±25V

T_{OUT} (Except MAX220) (Note 1) ..... ±15V

T_{OUT} (MAX220) ..... ±13.2V

Output Voltages

T_{OUT} ..... ±15V

R_{OUT} ..... -0.3V to (V_{CC} + 0.3V)

Driver/Receiver Output Short Circuited to GND ..... Continuous

Continuous Power Dissipation (T_A = +70°C)

16-Pin Plastic DIP (derate 10.53mW/°C above +70°C) 842mW

18-Pin Plastic DIP (derate 11.11mW/°C above +70°C) 889mW

20-Pin Plastic DIP (derate 5.00mW/°C above +70°C) 440mW

16-Pin Narrow SO (derate 8.70mW/°C above +70°C) 696mW

16-Pin Wide SO (derate 9.52mW/°C above +70°C) 762mW

18-Pin Wide SO (derate 9.52mW/°C above +70°C) 762mW

20-Pin Wide SO (derate 10.00mW/°C above +70°C) 800mW

20-Pin SSOP (derate 8.00mW/°C above +70°C) 640mW

16-Pin CERDIP (derate 10.00mW/°C above +70°C) 800mW

18-Pin CERDIP (derate 10.53mW/°C above +70°C) 842mW

Operating Temperature Ranges

MAX2_ _AC_ , MAX2_ _C_ ..... 0°C to +70°C

MAX2_ _AE_ , MAX2_ _E_ ..... -40°C to +85°C

MAX2_ _AM_ , MAX2_ _M_ ..... -55°C to +125°C

Storage Temperature Range ..... -65°C to +160°C

Lead Temperature (soldering, 10s) ..... +300°C

Note 1: Input voltage measured with T_{OUT} in high-impedance state, $\overline{SHDN}$ or V_{CC} = 0V.

Note 2: For the MAX220, V+ and V- can have a maximum magnitude of 7V, but their absolute difference cannot exceed 13V.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ELECTRICAL CHARACTERISTICS—MAX220/222/232A/233A/242/243

(V_{CC} = +5V ±10%, C1–C4 = 0.1µF, MAX220, C1 = 0.047µF, C2–C4 = 0.33µF, T_A = T_{MIN} to T_{MAX}, unless otherwise noted.)

PARAMETER	CONDITIONS		MIN	TYP	MAX	UNITS
RS-232 TRANSMITTERS						
Output Voltage Swing	All transmitter outputs loaded with 3kΩ to GND		±5	±8		V
Input Logic Threshold Low				1.4	0.8	V
Input Logic Threshold High	All devices except MAX220		2	1.4		V
	MAX220, V_{CC} = 5.0V		2.4			
Logic Pull-Up/Input Current	All except MAX220, normal operation			5	40	µA
	$\overline{SHDN}$ = 0V, MAX222/242, shutdown, MAX220			±0.01	±1	
Output Leakage Current	V_{CC} = 5.5V, $\overline{SHDN}$ = 0V, V_{OUT} = ±15V, MAX222/242			±0.01	±10	µA
	V_{CC} = $\overline{SHDN}$ = 0V, V_{OUT} = ±15V			±0.01	±10	
Data Rate				200	116	kbps
Transmitter Output Resistance	V_{CC} = V+ = V- = 0V, V_{OUT} = ±2V		300	10M		Ω
Output Short-Circuit Current	V_{OUT} = 0V			±7	±22	mA
RS-232 RECEIVERS						
RS-232 Input Voltage Operating Range					±30	V
RS-232 Input Threshold Low	V_{CC} = 5V	All except MAX243 $R2_{IN}$	0.8	1.3		V
		MAX243 $R2_{IN}$ (Note 2)	-3			
RS-232 Input Threshold High	V_{CC} = 5V	All except MAX243 $R2_{IN}$		1.8	2.4	V
		MAX243 $R2_{IN}$ (Note 2)		-0.8	-0.1	
RS-232 Input Hysteresis	All except MAX243, V_{CC} = 5V, no hysteresis in shdn.		0.2	0.5	1	V
	MAX243			1		
RS-232 Input Resistance			3	5	7	kΩ
TTL/CMOS Output Voltage Low	I_{OUT} = 3.2mA			0.2	0.4	V
TTL/CMOS Output Voltage High	I_{OUT} = -1.0mA		3.5	V_{CC} - 0.2		V
TTL/CMOS Output Short-Circuit Current	Sourcing V_{OUT} = GND		-2	-10		mA
	Shrinking V_{OUT} = V_{CC}		10	30		

ELECTRICAL CHARACTERISTICS—MAX220/222/232A/233A/242/243 (continued)

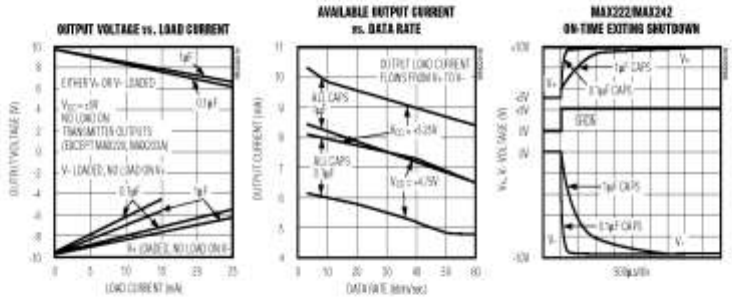
(V_{CC} = +5V ±10%, C1–C4 = 0.1µF, MAX220: C1 = 0.047µF, C2–C4 = 0.33µF, T_A = T_{MIN} to T_{MAX}, unless otherwise noted.)

PARAMETER	CONDITIONS		MIN	TYP	MAX	UNITS
TTL/CMOS Output Leakage Current	$\overline{SHDN}$ = V_{CC} or $\overline{EN}$ = V_{CC} ($\overline{SHDN}$ = 0V for MAX222), 0V ≤ V_{OUT} ≤ V_{CC}			±0.05	±10	µA
$\overline{EN}$ Input Threshold Low	MAX242			1.4	0.8	V
$\overline{EN}$ Input Threshold High	MAX242		2.0	1.4		V
Operating Supply Voltage			4.5		5.5	V
V_{CC} Supply Current ($\overline{SHDN}$ = V_{CC}), Figures 5, 6, 11, 19	No load	MAX220		0.5	2	mA
		MAX222/232A/233A/242/243		4	10	
	3kΩ load both inputs	MAX220		12		
		MAX222/232A/233A/242/243		15		
Shutdown Supply Current	MAX222/242	T_A = +25°C		0.1	10	µA
		T_A = 0°C to +70°C		2	50	
		T_A = -40°C to +85°C		2	50	
		T_A = -55°C to +125°C		35	100	
$\overline{SHDN}$ Input Leakage Current	MAX222/242				±1	µA
$\overline{SHDN}$ Threshold Low	MAX222/242			1.4	0.8	V
$\overline{SHDN}$ Threshold High	MAX222/242		2.0	1.4		V
Transition Slew Rate	C_L = 50pF to 2500pF, R_L = 3kΩ to 7kΩ, V_{CC} = 5V, T_A = +25°C, measured from +3V to -3V or -3V to +3V	MAX222/232A/233A/242/243	6	12	30	V/µs
		MAX220	1.5	3	30	
Transmitter Propagation Delay TTL to RS-232 (Normal Operation), Figure 1	t_{PHLT}	MAX222/232A/233A/242/243		1.3	3.5	µs
		MAX220		4	10	
	t_{PLHT}	MAX222/232A/233A/242/243		1.5	3.5	
		MAX220		5	10	
Receiver Propagation Delay RS-232 to TLL (Normal Operation), Figure 2	t_{PHLR}	MAX222/232A/233A/242/243		0.5	1	µs
		MAX220		0.6	3	
	t_{PLHR}	MAX222/232A/233A/242/243		0.6	1	
		MAX220		0.9	3	
Receiver Propagation Delay RS-232 to TLL (Shutdown), Figure 2	t_{PHLS}	MAX242		0.5	10	µs
	t_{PLHS}	MAX242		2.5	10	
Receiver-Output Enable Time, Figure 3	t_{ER}	MAX242		125	500	ns
Receiver-Output Disable Time, Figure 3	t_{DR}	MAX242		160	500	ns
Transmitter-Output Enable Time ($\overline{SHDN}$ Goes High), Figure 4	t_{ET}	MAX222/242, 0.1µF caps (includes charge-pump start-up)		250		µs
Transmitter-Output Disable Time ($\overline{SHDN}$ Goes Low), Figure 4	t_{DT}	MAX222/242, 0.1µF caps		600		ns
Transmitter + to - Propagation Delay Difference (Normal Operation)	t_{PHLT} - t_{PLHT}	MAX222/232A/233A/242/243		300		ns
		MAX220		2000		
Receiver + to - Propagation Delay Difference (Normal Operation)	t_{PHLR} - t_{PLHR}	MAX222/232A/233A/242/243		100		ns
		MAX220		225		

Note 3: MAX243 $R2_{OUT}$ is guaranteed to be low when $R2_{IN}$ is ≥ 0V or is floating.

Typical Operating Characteristics

MAX220/MAX222/MAX232A/MAX233A/MAX242/MAX243



Detailed Description

The MAX220–MAX249 contain four sections: dual charge-pump DC-DC voltage converters, RS-232 drivers, RS-232 receivers, and receiver and transmitter enable control inputs.

Dual Charge-Pump Voltage Converter

The MAX220–MAX249 have two internal charge-pumps that convert +5V to ±10V (unloaded) for RS-232 driver operation. The first converter uses capacitor C1 to double the +5V input to +10V on C3 at the V+ output. The second converter uses capacitor C2 to invert +10V to -10V on C4 at the V- output.

A small amount of power may be drawn from the +10V (V+) and -10V (V-) outputs to power external circuitry (see the *Typical Operating Characteristics* section), except on the MAX225 and MAX245–MAX247, where these pins are not available. V+ and V- are not regulated, so the output voltage drops with increasing load current. Do not load V+ and V- to a point that violates the minimum ±5V EIA/TIA-232E driver output voltage when sourcing current from V+ and V- to external circuitry.

When using the shutdown feature in the MAX222, MAX225, MAX230, MAX235, MAX236, MAX240, MAX241, and MAX245–MAX249, avoid using V+ and V- to power external circuitry. When these parts are shut down, V- falls to 0V, and V+ falls to +5V. For applications where a +10V external supply is applied to the V+ pin (instead of using the internal charge pump to generate +10V), the C1 capacitor must not be installed and the SHDN pin must be tied to V_{CC}. This is because V+ is internally connected to V_{CC} in shutdown mode.

RS-232 Drivers

The typical driver output voltage swing is ±8V when loaded with a nominal 5kΩ RS-232 receiver and V_{CC} = +5V. Output swing is guaranteed to meet the EIA/TIA-232E and V.28 specification, which calls for ±5V minimum driver output levels under worst-case conditions. These include a minimum 3kΩ load, V_{CC} = +4.5V, and maximum operating temperature. Unloaded driver output voltage ranges from (V+ -1.3V) to (V- +0.5V).

Input thresholds are both TTL and CMOS compatible. The inputs of unused drivers can be left unconnected since 400kΩ input pull-up resistors to V_{CC} are built in (except for the MAX220). The pull-up resistors force the outputs of unused drivers low because all drivers invert. The internal input pull-up resistors typically source 12µA, except in shutdown mode where the pull-ups are disabled. Driver outputs turn off and enter a high-impedance state—where leakage current is typically microamperes (maximum 25µA)—when in shutdown mode, in three-state mode, or when device power is removed. Outputs can be driven to ±15V. The power-supply current typically drops to 8µA in shutdown mode. The MAX220 does not have pull-up resistors to force the outputs of the unused drivers low. Connect unused inputs to GND or V_{CC}.

The MAX239 has a receiver three-state control line, and the MAX223, MAX225, MAX235, MAX295, MAX240, and MAX241 have both a receiver three-state control line and a low-power shutdown control. Table 2 shows the effects of the shutdown control and receiver three-state control on the receiver outputs.

The receiver TTL/CMOS outputs are in a high-impedance, three-state mode whenever the three-state enable line is high (for the MAX225/MAX235/MAX236/MAX239–MAX241), and are also high-impedance whenever the shutdown control line is high.

When in low-power shutdown mode, the driver outputs are turned off and their leakage current is less than 1µA with the driver output pulled to ground. The driver output leakage remains less than 1µA, even if the transmitter output is backdriven between 0V and (V_{CC} + 6V). Below -0.5V, the transmitter is diode clamped to ground with 1kΩ series impedance. The transmitter is also zener clamped to approximately V_{CC} + 6V, with a series impedance of 1kΩ.

The driver output slew rate is limited to less than 30V/µs as required by the EIA/TIA-232E and V.28 specifications. Typical slew rates are 24V/µs unloaded and 10V/µs loaded with 3kΩ and 2500pF.

RS-232 Receivers

EIA/TIA-232E and V.28 specifications define a voltage level greater than 3V as a logic 0, so all receivers invert. Input thresholds are set at 0.8V and 2.4V, so receivers respond to TTL level inputs as well as EIA/TIA-232E and V.28 levels.

The receiver inputs withstand an input overvoltage up to ±25V and provide input terminating resistors with nominal 5kΩ values. The receivers implement Type 1 interpretation of the fault conditions of V.28 and EIA/TIA-232E.

The receiver input hysteresis is typically 0.5V with a guaranteed minimum of 0.2V. This produces clear output transitions with slow-moving input signals, even with moderate amounts of noise and ringing. The receiver propagation delay is typically 600ns and is independent of input swing direction.

Table 2. Three-State Control of Receivers

PART	SHDN	SHDN	EN	EN(R)	RECEIVERS
MAX223	—	Low High High	X Low High	—	High Impedance Active High Impedance
MAX225	—	—	—	Low High	High Impedance Active
MAX235 MAX236 MAX240	Low Low High	—	—	Low High X	High Impedance Active High Impedance

Low-Power Receive Mode

The low-power receive-mode feature of the MAX223, MAX242, and MAX245–MAX249 puts the IC into shutdown mode but still allows it to receive information. This is important for applications where systems are periodically awakened to look for activity. Using low-power receive mode, the system can still receive a signal that will activate it on command and prepare it for communication at faster data rates. This operation conserves system power.

Negative Threshold—MAX243

The MAX243 is pin compatible with the MAX232A, differing only in that RS-232 cable fault protection is removed on one of the two receiver inputs. This means that control lines such as CTS and RTS can either be driven or left floating without interrupting communication. Different cables are not needed to interface with different pieces of equipment.

The input threshold of the receiver without cable fault protection is -0.8V rather than +1.4V. Its output goes positive only if the input is connected to a control line that is actively driven negative. If not driven, it defaults to the 0 or "OK to send" state. Normally, the MAX243's other receiver (+1.4V threshold) is used for the data line (TD or RD), while the negative threshold receiver is connected to the control line (DTR, DTS, CTS, RTS, etc.).

Other members of the RS-232 family implement the optional cable fault protection as specified by EIA/TIA-232E specifications. This means a receiver output goes high whenever its input is driven negative, left floating, or shorted to ground. The high output tells the serial communications IC to stop sending data. To avoid this, the control lines must either be driven or connected with jumpers to an appropriate positive voltage level.

Shutdown—MAX222–MAX242

On the MAX222, MAX235, MAX236, MAX240, and MAX241, all receivers are disabled during shutdown. On the MAX223 and MAX242, two receivers continue to operate in a reduced power mode when the chip is in shutdown. Under these conditions, the propagation delay increases to about 2.5µs for a high-to-low input transition. When in shutdown, the receiver acts as a CMOS inverter with no hysteresis. The MAX223 and MAX242 also have a receiver output enable input ($\overline{EN}$ for the MAX242 and EN for the MAX223) that allows receiver output control independent of $\overline{SHDN}$ (SHDN for MAX241). With all other devices, $\overline{SHDN}$ (SHDN for MAX241) also disables the receiver outputs.

The MAX225 provides five transmitters and five receivers, while the MAX245 provides ten receivers and eight transmitters. Both devices have separate receiver and transmitter-enable controls. The charge pumps turn off and the devices shut down when a logic high is applied to the $\overline{ENT}$ input. In this state, the supply current drops to less than 25µA and the receivers continue to operate in a low-power receive mode. Driver outputs enter a high-impedance state (three-state mode). On the MAX225, all five receivers are controlled by the $\overline{ENR}$ input. On the MAX245, eight of the receiver outputs are controlled by the $\overline{ENR}$ input, while the remaining two receivers (RA5 and RB5) are always active. RA1–RA4 and RB1–RB4 are put in a three-state mode when $\overline{ENR}$ is a logic high.

Receiver and Transmitter Enable Control Inputs

The MAX225 and MAX245–MAX249 feature transmitter and receiver enable controls.

The receivers have three modes of operation: full-speed receive (normal active), three-state (disabled), and low-power receive (enabled receivers continue to function at lower data rates). The receiver enable inputs control the full-speed receive and three-state modes. The transmitters have two modes of operation: full-speed transmit (normal active) and three-state (disabled). The transmitter enable inputs also control the shutdown mode. The device enters shutdown mode when all transmitters are disabled. Enabled receivers function in the low-power receive mode when in shutdown.

Tables 1a–1d define the control states. The MAX244 has no control pins and is not included in these tables.

The MAX246 has ten receivers and eight drivers with two control pins, each controlling one side of the device. A logic high at the A-side control input ($\overline{ENA}$) causes the four A-side receivers and drivers to go into a three-state mode. Similarly, the B-side control input ($\overline{ENB}$) causes the four B-side drivers and receivers to go into a three-state mode. As in the MAX245, one A-side and one B-side receiver (RA5 and RB5) remain active at all times. The entire device is put into shutdown mode when both the A and B sides are disabled ($\overline{ENA}$ = $\overline{ENB}$ = +5V).

The MAX247 provides nine receivers and eight drivers with four control pins. The $\overline{ENRA}$ and $\overline{ENRB}$ receiver enable inputs each control four receiver outputs. The $\overline{ENTA}$ and $\overline{ENTB}$ transmitter enable inputs each control four drivers. The ninth receiver (RB5) is always active. The device enters shutdown mode with a logic high on both $\overline{ENTA}$ and $\overline{ENTB}$.

The MAX248 provides eight receivers and eight drivers with four control pins. The $\overline{ENRA}$ and $\overline{ENRB}$ receiver enable inputs each control four receiver outputs. The $\overline{ENTA}$ and $\overline{ENTB}$ transmitter enable inputs control four drivers each. This part does not have an always-active receiver. The device enters shutdown mode and transmitters go into a three-state mode with a logic high on both $\overline{ENTA}$ and $\overline{ENTB}$.

The MAX249 provides ten receivers and six drivers with four control pins. The $\overline{ENRA}$ and $\overline{ENRB}$ receiver enable inputs each control five receiver outputs. The $\overline{ENTA}$ and $\overline{ENTB}$ transmitter enable inputs control three drivers each. There is no always-active receiver. The device enters shutdown mode and transmitters go into a three-state mode with a logic high on both $\overline{ENTA}$ and $\overline{ENTB}$. In shutdown mode, active receivers operate in a low-power receive mode at data rates up to 20kbits/sec.

Applications Information

Figures 5 through 25 show pin configurations and typical operating circuits. In applications that are sensitive to power-supply noise, V_{CC} should be decoupled to ground with a capacitor of the same value as C1 and C2 connected as close as possible to the device.

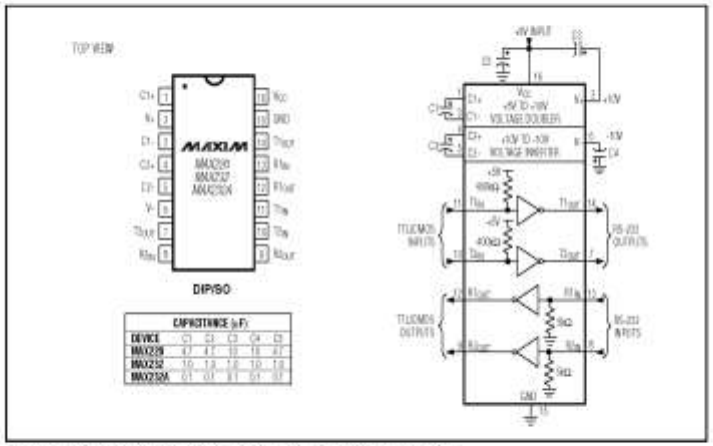


Figure 5. MAX220/MAX232/MAX232A Pin Configuration and Typical Operating Circuit

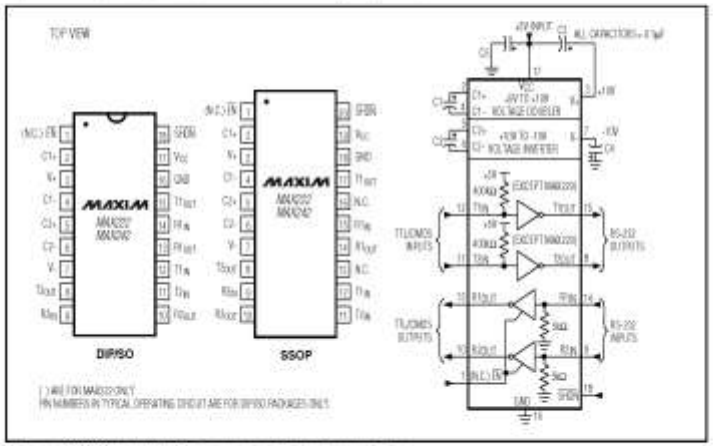


Figure 6. MAX222/MAX242 Pin Configurations and Typical Operating Circuit

Ordering Information (continued)

PART	TEMP RANGE	PIN-PACKAGE
MAX222CPN	0°C to +70°C	16 Plastic DIP
MAX222CWN	0°C to +70°C	16 Wide SO
MAX222C/D	0°C to +70°C	Dice*
MAX222EPN	-40°C to +85°C	16 Plastic DIP
MAX222EWN	-40°C to +85°C	16 Wide SO
MAX222EJN	-40°C to +85°C	16 CERDIP
MAX222MJN	-55°C to +125°C	16 CERDIP
MAX223CAI	0°C to +70°C	28 SSOP
MAX223CWI	0°C to +70°C	28 Wide SO
MAX223C/D	0°C to +70°C	Dice*
MAX223EAI	-40°C to +85°C	28 SSOP
MAX223EWI	-40°C to +85°C	28 Wide SO
MAX225CWI	0°C to +70°C	28 Wide SO
MAX225EWI	-40°C to +85°C	28 Wide SO
MAX230CPP	0°C to +70°C	20 Plastic DIP
MAX230CWP	0°C to +70°C	20 Wide SO
MAX230C/D	0°C to +70°C	Dice*
MAX230EPP	-40°C to +85°C	20 Plastic DIP
MAX230EWP	-40°C to +85°C	20 Wide SO
MAX230EJP	-40°C to +85°C	20 CERDIP
MAX230MJP	-55°C to +125°C	20 CERDIP
MAX231CPD	0°C to +70°C	14 Plastic DIP
MAX231CWE	0°C to +70°C	16 Wide SO
MAX231CJD	0°C to +70°C	14 CERDIP
MAX231C/D	0°C to +70°C	Dice*
MAX231EPD	-40°C to +85°C	14 Plastic DIP
MAX231EWE	-40°C to +85°C	16 Wide SO
MAX231EJD	-40°C to +85°C	14 CERDIP
MAX231MJD	-55°C to +125°C	14 CERDIP
MAX232CPE	0°C to +70°C	16 Plastic DIP
MAX232CSE	0°C to +70°C	16 Narrow SO
MAX232CWE	0°C to +70°C	16 Wide SO
MAX232C/D	0°C to +70°C	Dice*
MAX232EPE	-40°C to +85°C	16 Plastic DIP
MAX232ESE	-40°C to +85°C	16 Narrow SO
MAX232EWE	-40°C to +85°C	16 Wide SO
MAX232EJE	-40°C to +85°C	16 CERDIP
MAX232MJE	-55°C to +125°C	16 CERDIP
MAX232MLP	-55°C to +125°C	20 LCC
MAX232ACPE	0°C to +70°C	16 Plastic DIP
MAX232ACSE	0°C to +70°C	16 Narrow SO
MAX232ACWE	0°C to +70°C	16 Wide SO

PART	TEMP RANGE	PIN-PACKAGE
MAX232AC/D	0°C to +70°C	Dice*
MAX232AEPE	-40°C to +85°C	16 Plastic DIP
MAX232AESE	-40°C to +85°C	16 Narrow SO
MAX232AEWE	-40°C to +85°C	16 Wide SO
MAX232AEJE	-40°C to +85°C	16 CERDIP
MAX232AMJE	-55°C to +125°C	16 CERDIP
MAX232AMLP	-55°C to +125°C	20 LCC
MAX233CPP	0°C to +70°C	20 Plastic DIP
MAX233EPP	-40°C to +85°C	20 Plastic DIP
MAX233ACPP	0°C to +70°C	20 Plastic DIP
MAX233ACWP	0°C to +70°C	20 Wide SO
MAX233AEPP	-40°C to +85°C	20 Plastic DIP
MAX233AEWP	-40°C to +85°C	20 Wide SO
MAX234CPE	0°C to +70°C	16 Plastic DIP
MAX234CWE	0°C to +70°C	16 Wide SO
MAX234C/D	0°C to +70°C	Dice*
MAX234EPE	-40°C to +85°C	16 Plastic DIP
MAX234EWE	-40°C to +85°C	16 Wide SO
MAX234EJE	-40°C to +85°C	16 CERDIP
MAX234MJE	-55°C to +125°C	16 CERDIP
MAX235CPG	0°C to +70°C	24 Wide Plastic DIP
MAX235EPG	-40°C to +85°C	24 Wide Plastic DIP
MAX235EDG	-40°C to +85°C	24 Ceramic SB
MAX235MDG	-55°C to +125°C	24 Ceramic SB
MAX236CNG	0°C to +70°C	24 Narrow Plastic DIP
MAX236CWG	0°C to +70°C	24 Wide SO
MAX236C/D	0°C to +70°C	Dice*
MAX236ENG	-40°C to +85°C	24 Narrow Plastic DIP
MAX236EWG	-40°C to +85°C	24 Wide SO
MAX236ERG	-40°C to +85°C	24 Narrow CERDIP
MAX236MRG	-55°C to +125°C	24 Narrow CERDIP
MAX237CNG	0°C to +70°C	24 Narrow Plastic DIP
MAX237CWG	0°C to +70°C	24 Wide SO
MAX237C/D	0°C to +70°C	Dice*
MAX237ENG	-40°C to +85°C	24 Narrow Plastic DIP
MAX237EWG	-40°C to +85°C	24 Wide SO
MAX237ERG	-40°C to +85°C	24 Narrow CERDIP
MAX237MRG	-55°C to +125°C	24 Narrow CERDIP
MAX238CNG	0°C to +70°C	24 Narrow Plastic DIP
MAX238CWG	0°C to +70°C	24 Wide SO
MAX238C/D	0°C to +70°C	Dice*
MAX238ENG	-40°C to +85°C	24 Narrow Plastic DIP

* Contact factory for dice specifications.

Ordering Information (continued)

PART	TEMP RANGE	PIN-PACKAGE
MAX238EWG	-40°C to +85°C	24 Wide SO
MAX238ERG	-40°C to +85°C	24 Narrow CERDIP
MAX238MRG	-55°C to +125°C	24 Narrow CERDIP
MAX239CNG	0°C to +70°C	24 Narrow Plastic DIP
MAX239CWG	0°C to +70°C	24 Wide SO
MAX239C/D	0°C to +70°C	Dice*
MAX239ENG	-40°C to +85°C	24 Narrow Plastic DIP
MAX239EWG	-40°C to +85°C	24 Wide SO
MAX239ERG	-40°C to +85°C	24 Narrow CERDIP
MAX239MRG	-55°C to +125°C	24 Narrow CERDIP
MAX240CMH	0°C to +70°C	44 Plastic FP
MAX240C/D	0°C to +70°C	Dice*
MAX241CAI	0°C to +70°C	28 SSOP
MAX241CWI	0°C to +70°C	28 Wide SO
MAX241C/D	0°C to +70°C	Dice*
MAX241EAI	-40°C to +85°C	28 SSOP
MAX241EWI	-40°C to +85°C	28 Wide SO
MAX242CAP	0°C to +70°C	20 SSOP
MAX242CPN	0°C to +70°C	16 Plastic DIP
MAX242CWN	0°C to +70°C	16 Wide SO
MAX242C/D	0°C to +70°C	Dice*
MAX242EPN	-40°C to +85°C	16 Plastic DIP
MAX242EWN	-40°C to +85°C	16 Wide SO
MAX242EJN	-40°C to +85°C	16 CERDIP
MAX242MJN	-55°C to +125°C	16 CERDIP

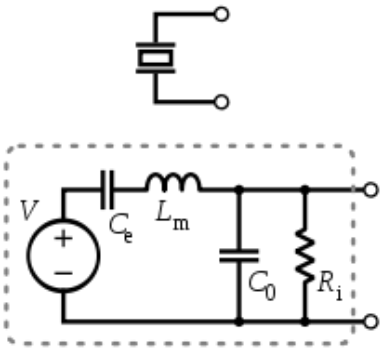
PART	TEMP RANGE	PIN-PACKAGE
MAX243CPE	0°C to +70°C	16 Plastic DIP
MAX243CSE	0°C to +70°C	16 Narrow SO
MAX243CWE	0°C to +70°C	16 Wide SO
MAX243C/D	0°C to +70°C	Dice*
MAX243EPE	-40°C to +85°C	16 Plastic DIP
MAX243ESE	-40°C to +85°C	16 Narrow SO
MAX243EWE	-40°C to +85°C	16 Wide SO
MAX243EJE	-40°C to +85°C	16 CERDIP
MAX243MJE	-55°C to +125°C	16 CERDIP
MAX244CQH	0°C to +70°C	44 PLCC
MAX244C/D	0°C to +70°C	Dice*
MAX244EQH	-40°C to +85°C	44 PLCC
MAX245CPL	0°C to +70°C	40 Plastic DIP
MAX245C/D	0°C to +70°C	Dice*
MAX245EPL	-40°C to +85°C	40 Plastic DIP
MAX246CPL	0°C to +70°C	40 Plastic DIP
MAX246C/D	0°C to +70°C	Dice*
MAX246EPL	-40°C to +85°C	40 Plastic DIP
MAX247CPL	0°C to +70°C	40 Plastic DIP
MAX247C/D	0°C to +70°C	Dice*
MAX247EPL	-40°C to +85°C	40 Plastic DIP
MAX248CQH	0°C to +70°C	44 PLCC
MAX248C/D	0°C to +70°C	Dice*
MAX248EQH	-40°C to +85°C	44 PLCC
MAX249CQH	0°C to +70°C	44 PLCC
MAX249EQH	-40°C to +85°C	44 PLCC

* Contact factory for dice specifications.

Package Information

For the latest package outline information, go to
www.maxim-ic.com/packages

Lampiran K
Persamaan (2 – 2)



$$Z_1 = \frac{R_i}{R_i C_o s + 1}$$

$$V_o(s) = \frac{\frac{R_i}{R_i C_o s + 1}}{\frac{R_i}{R_i C_o s + 1} + \frac{1}{C_e s} + L_m s} V_i(s)$$

$$V_o(s) = \frac{R_i\ C_e\ s}{R_i\ C_e\ s + R_i\ C_o\ s + 1 + R_i\ C_e\ C_o\ L_m\ s^3 + C_e L_m\ s} V_i(s)$$

$$\frac{V_o(s)}{V_i(s)} = \frac{R_i\ C_e\ s}{R_i\ s\ (C_e + C_o + C_o\ C_e\ L_m s^2) + C_e L_m\ s^2 + 1}$$